

Low Quiescent Current USB Type-C Power Delivery Controller

1 General Description

The RT7211 is a low quiescent current USB Type-C Power Delivery (PD) controller designed for flexible source or sink applications. The embedded MCU and Bi-phase Mark Coding (BMC) transmitter manage PD protocol communication, while integrated DAC and ADC modules deliver precise voltage and current regulation. As a source controller, it is suitable for off-line AC-DC converters, or for DC-DC converter applications such as car chargers when used with an external buck or buck-boost controller. As a sink controller, it offers a simple and cost-effective solution for power negotiation, featuring an I²C interface and two GPIOs for enhanced flexibility and easy integration with an external MCU.

The recommended junction temperature range is -40°C to 125°C, and the ambient temperature range is -40°C to 105°C.

2 Applications

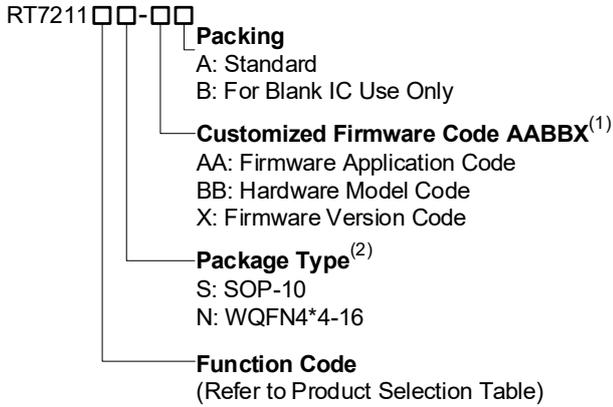
- USB Type-C PD Controller in Source Application for Chargers/Adapters of Smartphone, Tablet, Notebook, and Other Electronics
- USB Type-C PD Controller in Sink Application for IoT Devices of Power Over Ethernet, Smart Speaker, Projector, and Other Electronics

3 Features

- **Protocol Support**
 - USB PD3.2 PPS and SPR AVS
- **Operation**
 - Wide Voltage Range from 3.3V to 21V
 - < 9mA Operating Current in Normal Mode
 - < 0.5mA Operating Current in Sleep Mode
 - < 0.35mA Operating Current in Green Mode
- **System Management**
 - ARM Cortex-M0 Microcontroller with 10.8MHz Oscillator and MTP-ROM of 16kB (Supports OTP via FT Trim)
 - 11-bit ADCs for Reading Information on Pins
 - 11-bit DACs for Constant-Voltage and 10-bit DACs Constant-Current Regulations
 - I²C Slave (100kHz) Interface
 - V5 External LDO Output for PFC/LED Control
- **Power Management**
 - Linear Cable Compensation
 - VDD Pin Discharger for Output Capacitor
 - USBP Pin or GPIO Pin Discharger for Vsafe0V
- **Port Management**
 - Built-In N-MOSFET Driver
 - Built-in 8-bit DAC for Capacitive-Load Start-up
 - Built-in 100mW VCONN Power
 - Firmware Online-Update Supported
- **Protection**
 - VDD Adaptive Overvoltage Protection
 - VDD Adaptive Undervoltage Protection
 - VDD Drop for Short-Circuit Protection
 - Limited Power Source Protection
 - Programmable Overcurrent Protection
 - Programmable External and Internal Over-Temperature Protection

4 Ordering Information

4.1 Product Number Information



Note 1.

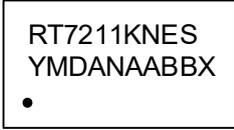
- Marked with ⁽¹⁾ indicated: If the firmware code is empty, this field will be removed.
- Marked with ⁽²⁾ indicated: Compatible with the current requirements of IPC/JEDEC J-STD-020.

4.2 Product Selection Table

Function Code	KS	KT	KTL	KD	KNE	KNH	KA
Application Type	Sink	Source	Source	Source	Source	Source	Source
Package	WQFN-16L 4x4	WQFN-16L 4x4	WQFN-16L 4x4	SOP-10	SOP-10	SOP-10	SOP-10
Constant Current	O	O	O	O	O	X	X
Differential Current Sensing	O	O	O	O	X	O	O
V5 Pin	O	O	O	O	X	X	X
DP Pin	O	O	X	X	X	X	X
DM Pin	O	O	O	X	X	X	X
Max. Number of GPIOs	7 + 1(initial low)	8 + 1(initial low)	7 + 1(initial low)	2 + 1(initial low)	4 + 1(initial low)	3 + 1(initial low)	3 + 1(initial low)
VDD ROC	3.3V to 22V	3.3V to 21V	3.3V to 22V				

5 Marking Information

RT7211KNES-AABBX



RT7211KNES: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

RT7211KTN-AABBX



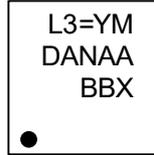
L2=: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

RT7211KNHS-AABBX



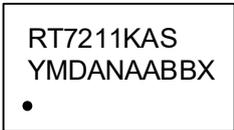
RT7211KNHS: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

RT7211KSN-AABBX



L3=: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

RT7211KAS-AABBX



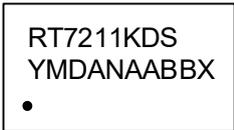
RT7211KAS: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

RT7211KTLN-AABBX



02J: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

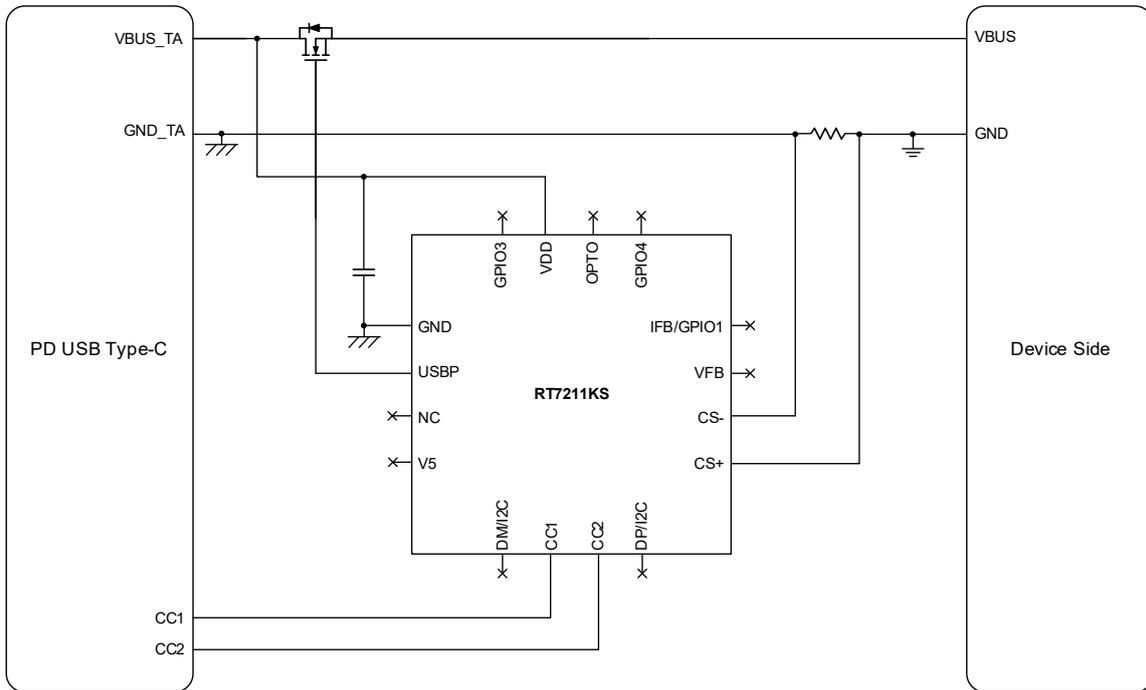
RT7211KDS-AABBX



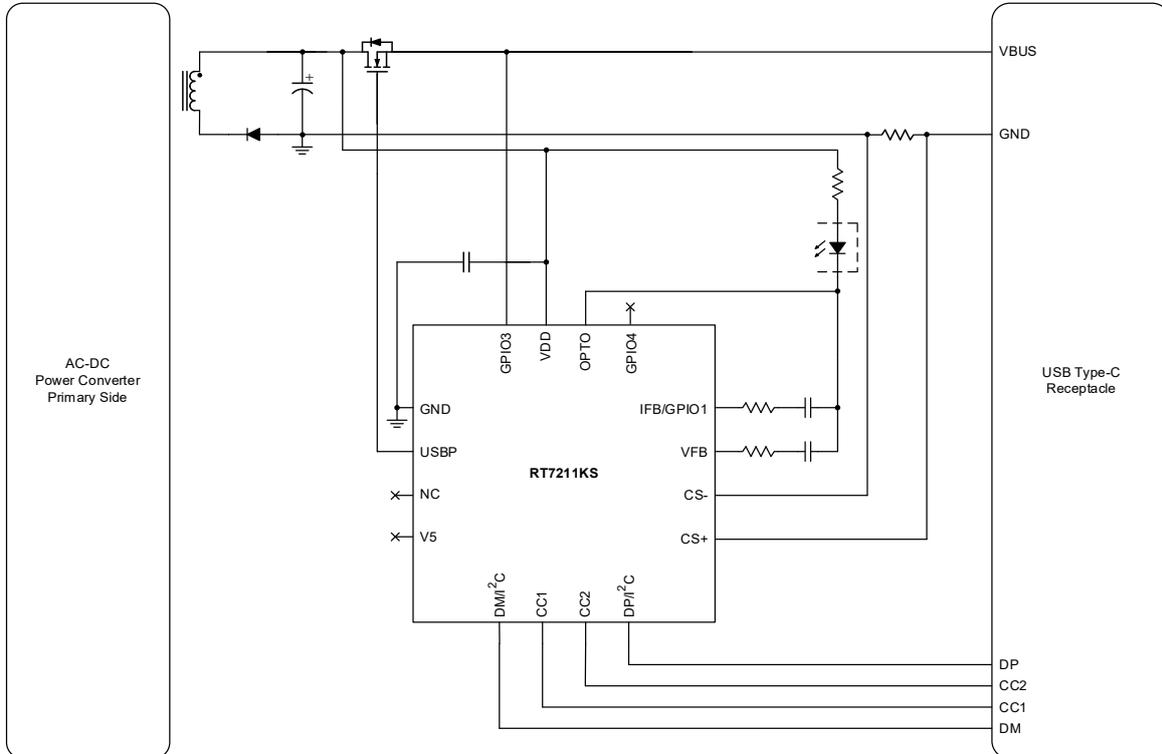
RT7211KDS: Product Code
YMDAN: Date Code
AABBX: Customized Firmware Code

6 Simplified Application Circuit

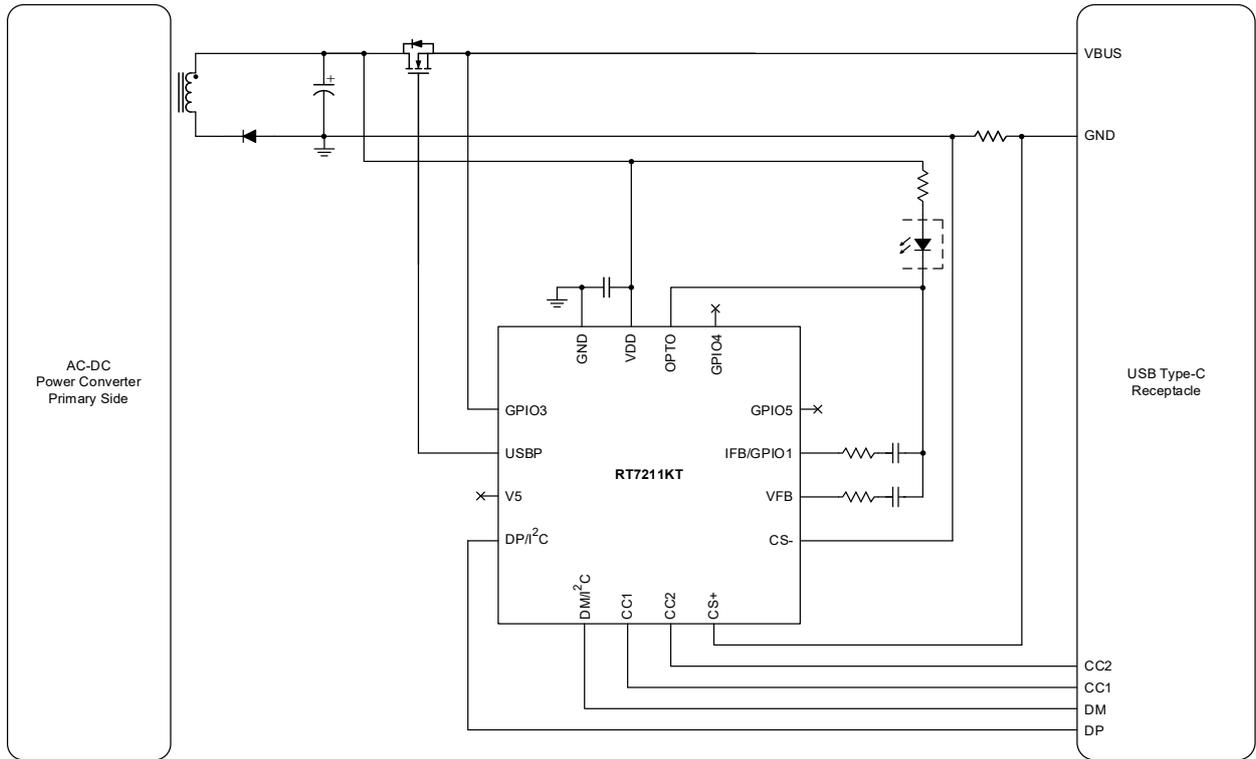
6.1 The RT7211KS Simplified Application Circuit for Sink Side



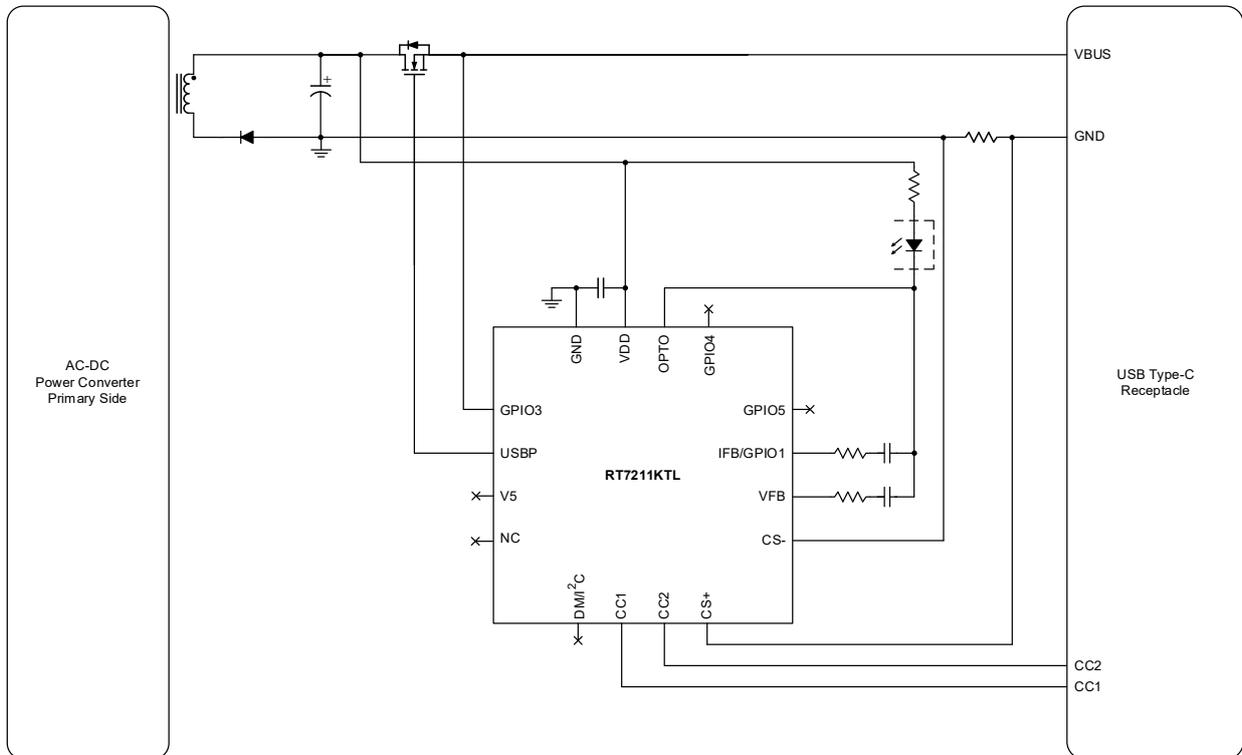
6.2 The RT7211KS Simplified Application Circuit for Source Side



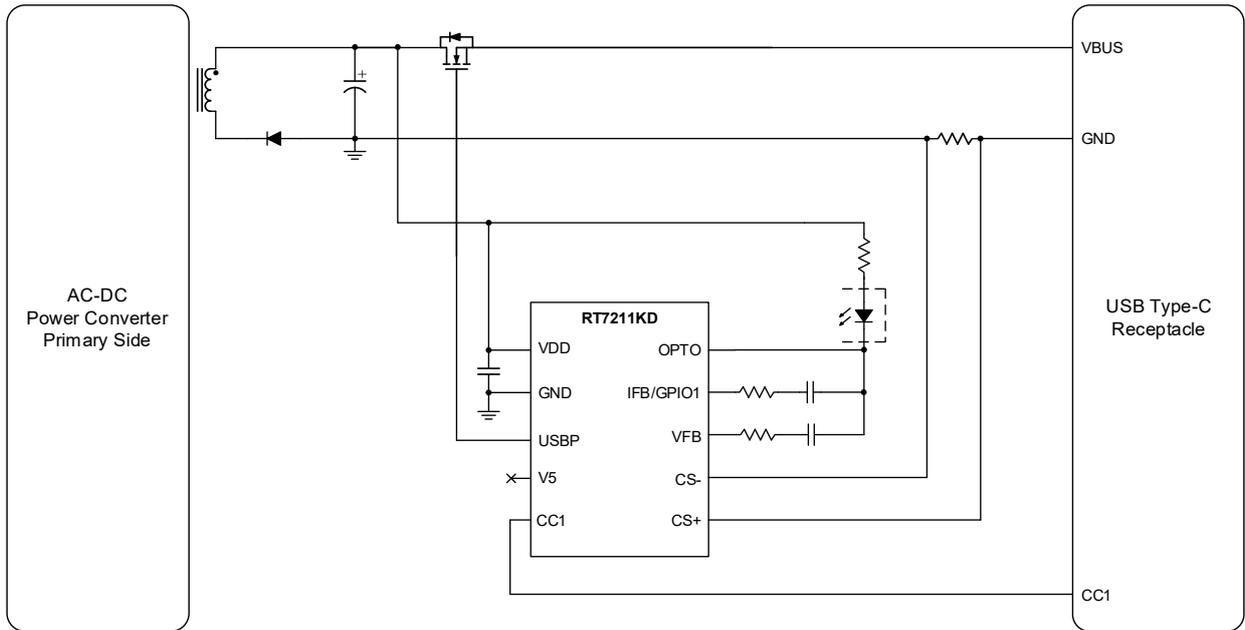
6.3 The RT7211KT Simplified Application Circuit for Source Side



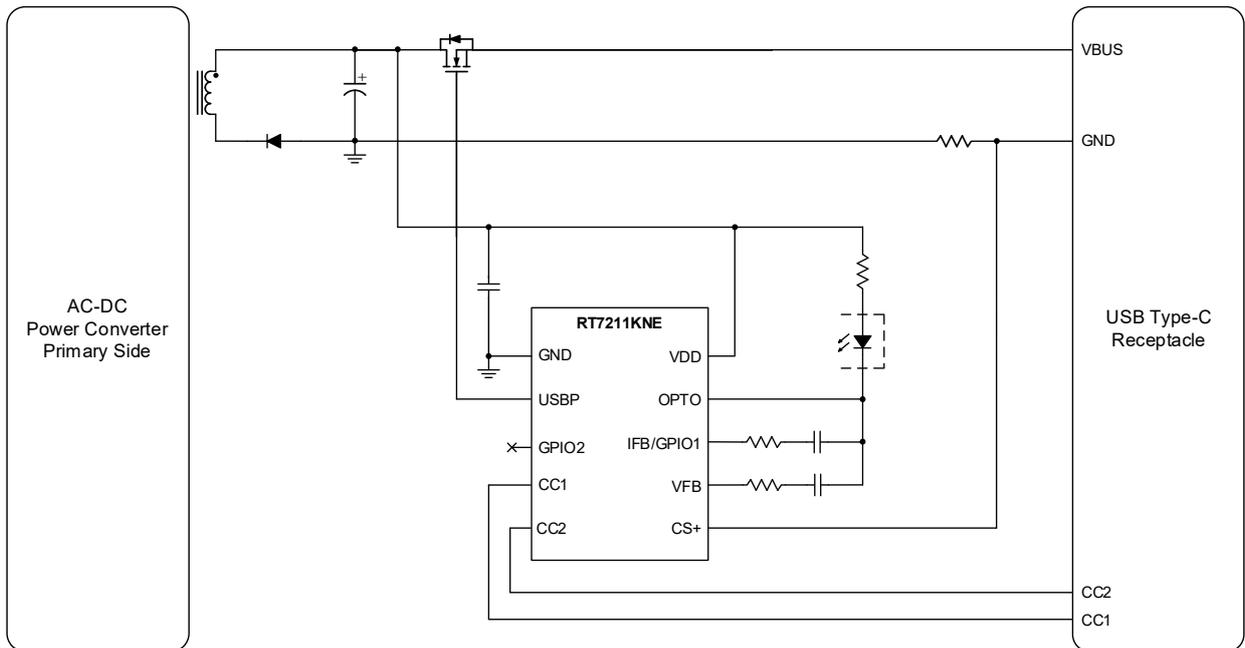
6.4 The RT7211KTL Simplified Application Circuit for Source Side



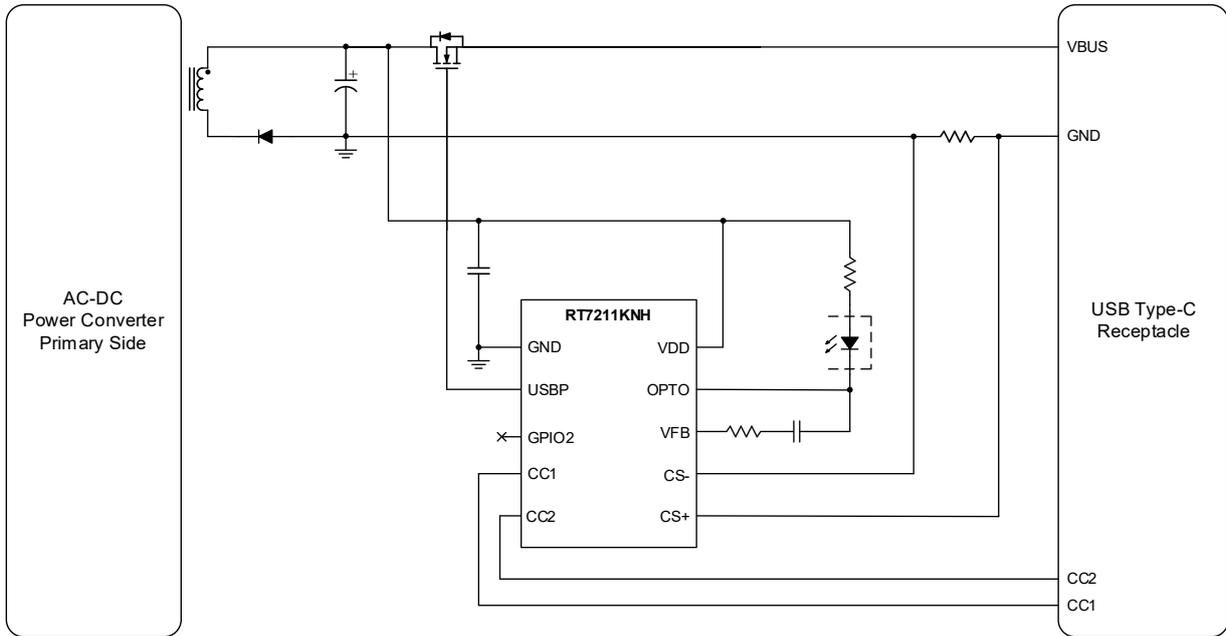
6.5 The RT7211KD Simplified Application Circuit for Source Side



6.6 The RT7211KNE Simplified Application Circuit for Source Side



6.7 The RT7211KNH Simplified Application Circuit for Source Side



6.8 The RT7211KA Simplified Application Circuit for Source Side

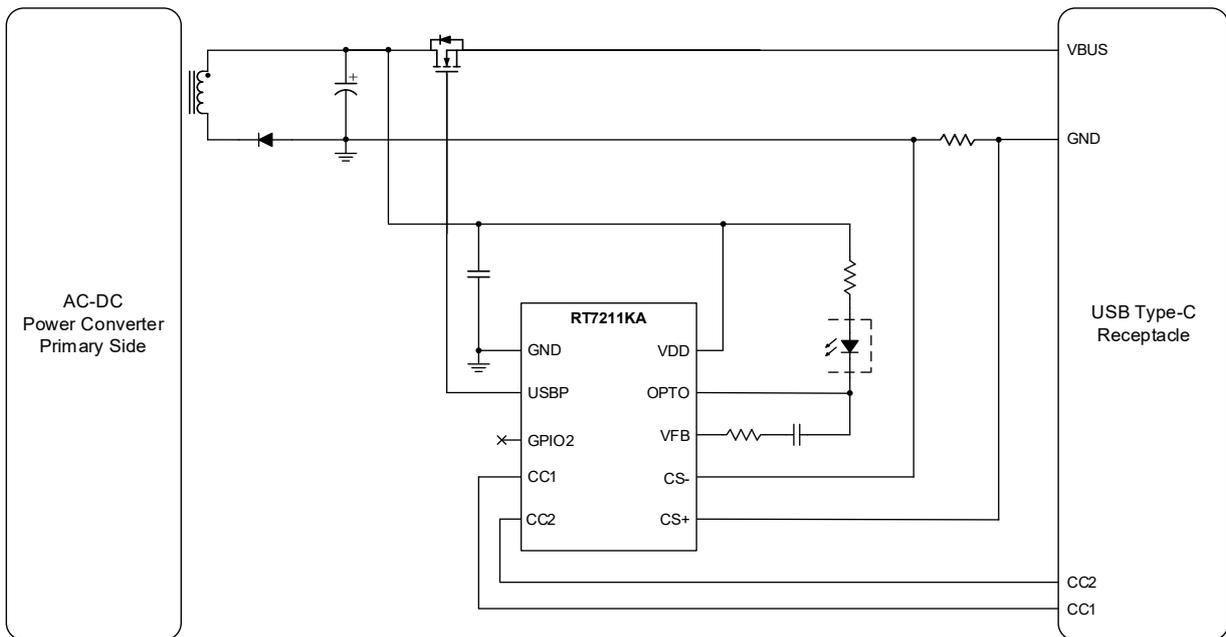
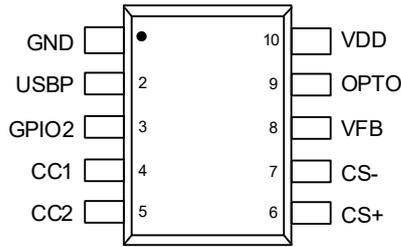


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SOP-10 (RT7211KA)

8 Functional Pin Description

8.1 For the RT7211KS / RT7211KT / RT7211KTL in WQFN Package

Pin No.			Pin Name	Type	Pin Function
RT7211KS	RT7211KT	RT7211KTL			
1	16	16	GND	GND	Ground.
2	2	2	USBP	A/D IO	General purpose input and open-drain output. (Initial low) Built-in charge pump and pull-down discharger for driving N-MOSFET and Vsafe0V
3	--	--	NC	--	No internal connection.
4	3	3	V5	PWR	5V Low-dropout regulator output
5	5	5	DM/I ² C	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20μA/100μA or sourcing voltage 4.5V with 3.1kΩ pull-up resistance, or as ADC input. Can be configured as I ² C SDA or SCL. Can be configured as UART_TX/UART_RX.
6	6	6	CC1	A/D IO	General purpose input and open-drain output. USB Type-C Configuration Channel 1: Built-in sourcing current for Source Advertisement, VCONN power, and BMC transceiver for USB PD. Can be configured as built-in sourcing current for rust detection.
7	7	7	CC2	A/D IO	General purpose input and open-drain output. USB Type-C Configuration Channel 2: Built-in sourcing current for Source Advertisement, VCONN power, and BMC transceiver for USB PD. Can be configured as built-in sourcing current for rust detection.
8	4	--	DP/I ² C	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20μA/100μA or sourcing voltage 4.5V with 3.1kΩ pull-up resistance, or as ADC input. Can be configured as I ² C SDA or SCL. Can be configured as UART_TX/UART_RX.
9	8	8	CS+	AI	Positive input of a current-sense amplifier for output current sensing.
10	9	9	CS-	AI	Negative input of a current-sense amplifier for output current sensing.

Pin No.			Pin Name	Type	Pin Function
RT7211KS	RT7211KT	RT7211KTL			
11	10	10	VFB	AI	Feedback input for the constant-voltage loop.
12	11	11	IFB/GPIO1	A/D IO	General purpose input and open-drain output. Compensation for constant-current loop. Connect a compensation network to stabilize the control loop. Can be configured as sourcing current 20 μ A/100 μ A/1100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
--	12	12	GPIO5	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20 μ A/100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
13	13	13	GPIO4	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20 μ A/100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
14	14	14	OPTO	A/D IO	Current sink output for optocoupler connection Can be configured as ADC input.
15	15	15	VDD	PWR	Supply input voltage.
16	1	1	GPIO3	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20 μ A/100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
17 (Exposed Pad)			GND	GND	Power ground. The exposed pad must be connected to GND and well soldered to a large PCB copper area for maximum power dissipation.

8.2 For the RT7211KD / RT7211KNE / RT7211KNH / RT7211KA in SOP-10 Package

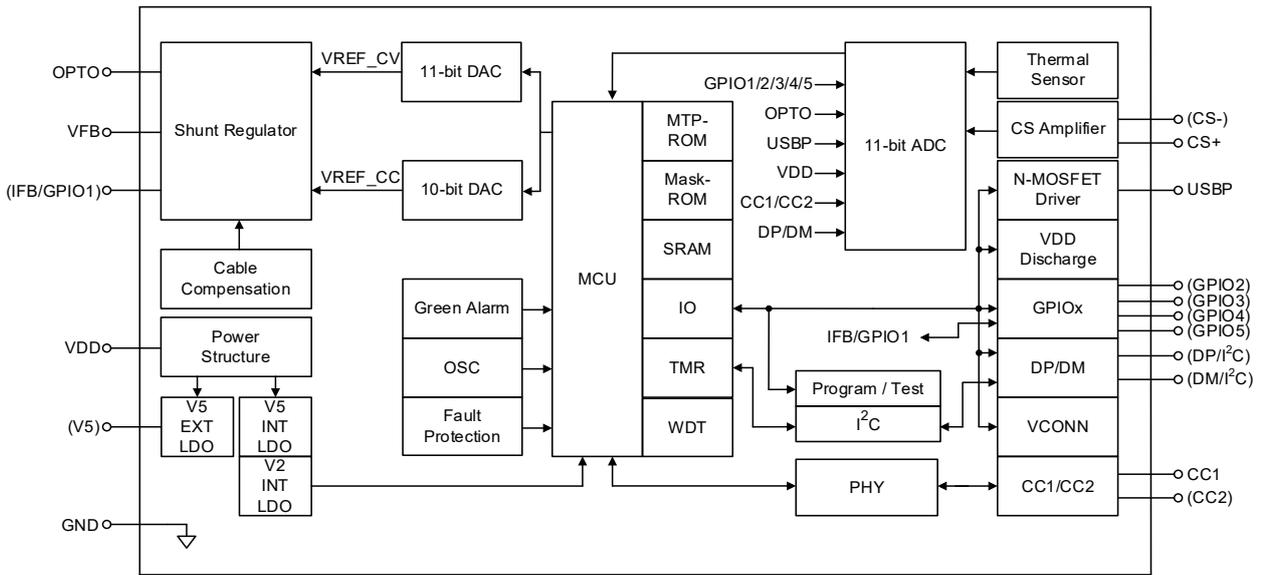
Pin No.				Pin Name	Type	Pin Function
RT7211KD	RT7211KNE	RT7211KNH	RT7211KA			
1	10	10	10	VDD	PWR	Supply input voltage.
2	1	1	1	GND	GND	Ground.
--	3	3	3	GPIO2	A/D IO	General purpose input and open-drain output. Can be configured as sourcing current 20 μ A/100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
3	2	2	2	USBP	A/D IO	General purpose input and open-drain output (Initial low). Built-in charge pump and pull-down discharger for driving N-MOSFET and Vsafe0V.
4	--	--	--	V5	PWR	5V low-dropout regulator output
5	4	4	4	CC1	A/D IO	General purpose input and open-drain output. USB Type-C Configuration Channel 1: Built-in sourcing current for Source Advertisement, VCONN power, and BMC transceiver for USB PD. Can be configured as built-in sourcing current for

Pin No.				Pin Name	Type	Pin Function
RT7211 KD	RT7211 KNE	RT7211 KNH	RT7211 KA			
						rust detection.
--	5	5	5	CC2	A/D IO	General purpose input and open-drain output. USB Type-C Configuration Channel 2: Built-in sourcing current for Source Advertisement, VCONN power, and BMC transceiver for USB PD. Can be configured as built-in sourcing current for rust detection.
6	6	6	6	CS+	AI	Positive input of a current-sense amplifier for output current sensing.
7	--	7	7	CS-	AI	Negative input of a current-sense amplifier for output current sensing.
8	7	8	8	VFB	AI	Feedback input for the constant-voltage loop.
9	8	--	--	IFB/GPIO1	A/D IO	General purpose input and open-drain output. Compensation for constant-current loop. Connect a compensation network to stabilize the control loop. Can be configured as sourcing current 20 μ A/100 μ A/1100 μ A or sourcing voltage 4.5V with 3.1k Ω pull-up resistance, or as ADC input.
10	9	9	9	OPTO	A/D IO	Current sink output for optocoupler connection. Can be configured as ADC input.

8.3 IO Type Definition

- PWR: Power Pin
- GND: Ground Pin
- AI: Analog Input Pin
- AO: Analog Output Pin
- A IO: Analog Input/Output Pin
- D I: Digital Input Pin
- D IO: Digital Input/Output Pin
- A/D IO: Analog/Digital Input/Output Pin

9 Functional Block Diagram



10 Absolute Maximum Ratings

(Note 2)

- USBP to GND ----- -0.3V to 35V
- VDD ----- -0.3V to 30V
- OPTO, VFB, IFB/GPIO1, GPIO2, GPIO3,
GPIO4, GPIO5, DP/I²C, DM/I²C, CC1, CC2, to GND ----- -0.3V to 28V
- CS+, CS-, V5 to GND----- -0.3V to 6.5V
- Power Dissipation, P_D @ T_A = 25°C
 - WQFN-16L 4x4 ----- 0.79W
 - SOP-10----- 0.73W
- Package Thermal Resistance (Note 3)
 - WQFN-16L 4x4, θ_{JA}----- 127.44°C/W
 - WQFN-16L 4x4, θ_{JC} ----- 35.7°C/W
 - SOP-10, θ_{JA}----- 137.29°C/W
 - SOP-10, θ_{JC} ----- 39.9°C/W
- Junction Temperature ----- 150°C
- Lead Temperature (Soldering, 10sec.)----- 260°C
- Storage Temperature Range ----- -65°C to 150°C
- ESD Susceptibility (Note 4)
 - HBM (Human Body Model)----- 2kV

Note 2. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Note 3. θ_{JA} is simulated under natural convection (still air) at T_A = 25°C with the component mounted on a low effective-thermal-conductivity single-layer test board on a JEDEC 51-3 thermal measurement standard. θ_{JC} is simulated at the bottom of the package.

Note 4. Devices are ESD sensitive. Handling precautions are recommended.

11 Recommended Operating Conditions

(Note 5)

- Supply Input Voltage, V_{DD} (RT7211KT, RT7211KTL, RT7211KD, RT7211KNE, RT7211KNH)----- 3.3V to 21V
- Supply Input Voltage, V_{DD} (RT7211KS, RT7211KA) ----- 3.3V to 22V
- Junction Temperature Range ----- -40°C to 125°C
- Ambient Temperature Range ----- -40°C to 105°C

Note 5. The device is not guaranteed to function outside its operating conditions.

12 Electrical Characteristics

(T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
PMU Section						
Oscillator Frequency for MCU	fOSC_MCU	VDD > 2.8V	10.26	10.80	11.34	MHz
BASE Section						
Internal V5 LDO Regulation Voltage	V _{V5}	5V < VDD < 21V 0mA < ILOAD < 5mA	4.61	4.85	5.09	V
Internal V5 LDO Output Short-Circuit Current	I _{V5_SC}		10	20	30	mA
VDD Section						
VDD Turn-On Threshold Voltage	VDD_ON		2.9	3.1	3.3	V
VDD Turn-Off Threshold Voltage	VDD_OFF		2.7	2.9	3.1	V
VDD Start-Up Current	I _{DD_STA}	VDD = 2.5V	--	0.2	0.3	mA
VDD Normal-Mode Current	I _{DD_NOR}	VDD = 3.3V to 21V Does not include I _{CC_SRC} and GPIO bias current	--	7.6	9	mA
VDD Idle-Mode Current	I _{DD_IDLE}	VDD = 3.3V to 21V Does not include I _{CC_SRC} and GPIO bias current	--	0.35	0.5	mA
VDD Green-Mode Current	I _{DD_GREEN}	VDD = 5V Does not include I _{CC_SRC} and GPIO bias current	--	0.25	0.35	mA
VDD Sinking Current for Output Voltage Discharge	I _{VDD_DSCHG}		21	30	39	mA
			42	60	78	
			63	90	117	
			84	120	156	
			105	150	195	
			126	180	234	
VDD Resistor Divider for Voltage Feedback	R _{VDD_FB}	R _{VDD_FB} = R _{FB1} + R _{FB2} R _{FB1} = 378kΩ, R _{FB2} = 42kΩ (Note 6)	294	420	546	kΩ
VDD Resistor Divider Scaling Factor for Voltage Feedback	K _{VDD_FB}		9.9	10	10.1	--
VDD Resistor Divider for ADC and Protection	R _{VDD_ADC}	(Note 6)	700	1000	1300	kΩ
VDD Resistor Divider Scaling Factor for ADC and Protection	K _{VDD_ADC}		9.9	10	10.1	--
Standby Output Voltage by Initial Reference	V _{VDD_ST}		0.485	0.5	0.515	V

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
VDD Threshold Voltage for Maximum Overvoltage Protection	V _{VDD_MOVP}		RT7211KS, RT7211KT, RT7211KTL, RT7211KD, RT7211KNE, RT7211KNH			
			23.5	24	25	V
			RT7211KA			
			24	24.5	25.5	V
VDD Maximum Overvoltage Protection Deglitch Time	t _{VDD_MOVP}	(Note 6)	25	30	35	μs
VDD Threshold Voltage for Adaptive Overvoltage Protection	V _{VDD_OVP}	110% (min) to 160% (max), adjustable in 2.5% steps	104.50	110.00	115.50	%
			152.00	160.00	168.00	
VDD Adaptive Overvoltage Protection Deglitch Time	t _{VDD_OVP}	8.5μs (min) to 53.5μs (max), adjustable in 3μs steps (Note 6)	7.14	8.50	9.86	μs
			44.94	53.50	62.06	
VDD Threshold Voltage for Adaptive Undervoltage Protection	V _{VDD_UVP}	52.5% (min) to 90% (max), adjustable in 2.5% steps	85.50	90.00	94.50	%
			49.88	52.50	55.13	
VDD Adaptive Undervoltage Protection Deglitch Time	t _{VDD_UVP}	8.5μs (min) to 53.5μs (max), adjustable in 3μs steps (Note 6)	7.14	8.50	9.86	μs
			44.94	53.50	62.06	
DAC/ADC Section						
Maximum DAC Output Voltage for Constant-Voltage Regulator	V _{DAC_CV_MAX}	11-bit digital-to-analog converter	RT7211KS, RT7211KT, RT7211KTL, RT7211KD, RT7211KNE, RT7211KNH			
			2.156	2.2	2.244	V
			RT7211KA			
			2.206	2.25	2.294	V
Minimum DAC Output Voltage for Constant-Voltage Regulator	V _{DAC_CV_MIN}		--	0.152	--	V
Maximum DAC Output Voltage for Constant-Current Regulator	V _{DAC_CC_MAX}	10-bit digital-to-analog converter	RT7211KS, RT7211KT, RT7211KTL, RT7211KD, RT7211KNE, RT7211KNH			
			0.147	1.5	1.53	V
			RT7211KA			
			0.181	1.534	1.564	V
Minimum DAC Output Voltage for Constant-Current Regulator	V _{DAC_CC_MIN}		--	0	--	V
Maximum ADC Sense Voltage	V _{ADC_MAX}	11-bit analog to digital converter	RT7211KS, RT7211KT, RT7211KTL, RT7211KD, RT7211KNE, RT7211KNH			
			2.178	2.2	2.222	V
			RT7211KA			
			2.228	2.25	2.272	V

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Current Sense Amplifier Section						
Current-Sense Amplifier Gain	KCS		19.4	20	20.6	V/V
			29.2	30	30.8	
Current-Sense Amplifier Output Offset Voltage	VCS_OFFSET		0.35	0.4	0.45	V
Cable-Compensation Resistance	RCABLE		20	25	30	mΩ
			40	50	60	
			63	75	85	
			90	100	110	
			105	125	145	
			130	150	170	
			180	200	220	
Current-Sense Amplifier Input Threshold Voltage for Current Wake-Up	VCS_WK	$V_{CS_WK} = (V_{CS+} - V_{CS-}) \times K_{CS} + V_{CS_OFFSET}$	0.51	0.55	0.59	V
			0.7117	0.75	0.7883	
			0.7508	0.7875	0.8242	
			0.7775	0.8125	0.8475	
			0.8042	0.8375	0.8708	
			0.8683	0.9	0.9317	
			0.8825	0.9125	0.9425	
			0.9217	0.95	0.9783	
			0.9483	0.975	1.0017	
			0.975	1	1.025	
			1.0142	1.0375	1.0608	
			1.0533	1.075	1.0967	
			1.08	1.1	1.12	
			1.1317	1.15	1.1683	
1.1833	1.2	1.2167				
1.235	1.25	1.265				
OPTO Section						
OPTO Pull-Up Resistance	ROPTO_PU	Pulled up to VDD	35.7	51	66.3	kΩ
OPTO Pull-Down Resistance	ROPTO_PD	Pulled down to GND	42	60	78	kΩ
OPTO Sinking Current	IOPTO_SINK		18.75	25	31.25	μA
OPTO Output-Low Resistance	ROPTO_OL	Shorted to GND	--	25	200	Ω
USBP Section						
USBP Turn-On Voltage	VUSBP_ON	RLOAD = 10MΩ	VDD + 7	VDD + 8.5	VDD + 10	V
		RLOAD = 1MΩ	VDD + 5	--	--	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
USBP Turn-On Soft-Start Time	tUSBP_SS	(Note 6)	0.9	1	1.1	ms
			1.8	2	2.2	
			3.6	4	4.4	
			7.2	8	8.8	
			14.4	16	17.6	
			28.8	32	35.2	
			57.6	64	70.4	
			115.2	128	140.8	
USBP Input Comparator Voltage for Vsafe0V	VUSBP_Vsafe0V		0.1	0.145	0.19	V
			0.9	1	1.1	
CC1/CC2 Section						
CC1/CC2 Sourcing Current	ICC_SRC	VDD > 3V (For precise bias current application)	18	20	22	μA
			72	80	88	
			169	180	191	
			304	330	356	
CC1/CC2 Sourcing Current Clamping Voltage	VCC_CLP		4	4.5	5	V
			2.9	3.25	3.6	
CC1/CC2 Input-High Threshold Voltage	VCC_IH		2.5	2.6	2.7	V
			1.5	1.6	1.7	
			1.9	2	2.1	
			0.9	1	1.1	
CC1/CC2 Threshold Voltage for Overvoltage Protection	VCC_OVP		5.75	6	6.25	V
CC1/CC2 Overvoltage Protection Deglitch Time	tCC_OVP	(Note 6)	0.09	0.1	0.11	ms
VCONN Section						
VCONN Voltage	VCONN	VDD = 5V, ICONN = 0mA	4.6	4.8	5	V
		VDD = 5V, ICONN = 33mA	3.8	--	--	
VCONN Short-Circuit Current	ICONN_SC	Short to 2V	45	70	95	mA
PD PHY Section						
BMC Transmitter Output-High Voltage	VOH_BMC		1.05	1.125	1.2	V
BMC Transmitter Output-Low Voltage	VOL_BMC		0	0.0375	0.075	V
BMC Transmitter Output On-Resistance	RON_BMC		15	35	55	Ω
BMC Transmitter Output Voltage Rise Time	tR_BMC		300	--	700	ns
BMC Transmitter Output Voltage Fall Time	tF_BMC		300	--	700	ns

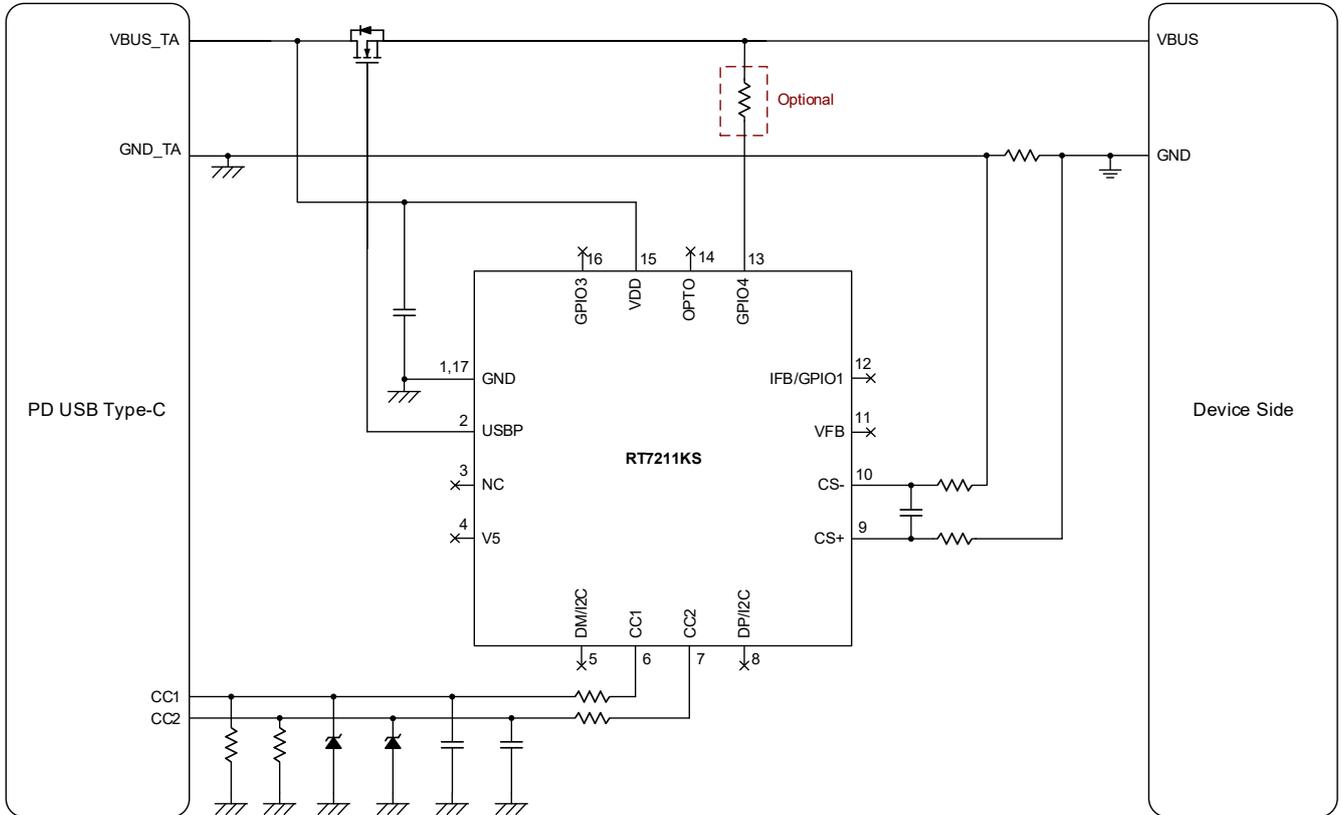
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
DP/DM Section						
DP/DM Sourcing Current	IDPDM_SRC	VDD > 3V (For precise bias current application)	18	20	22	μA
			95	100	105	
DP/DM Sourcing Current Clamping Voltage	VDPDM_CLP	VDD = 5V, IDPDM_BIAS = 95μA	3.6	4	5	V
		VDD = 5V, IDPDM_BIAS = 0μA	--	--	5	
DP/DM Sourcing Voltage	VDPDM_SRC	VDD = 5V, ILOAD = 1mA	1.2	2.1	3	V
		VDD = 5V, ILOAD = 10μA	4	4.5	5	
DP/DM Pull-Up Resistance	RDPDM_PU		1.65	3.1	4.65	kΩ
DP/DM Pull-Down Resistance	RDPDM_PD		16	20	24	kΩ
Dedicated Charging Port Resistance Across DP/DM	RDCP_DAT		--	--	40	Ω
DP/DM Output-Low Voltage	VDPDM_OL		--	--	0.2	V
DP/DM Input-High Threshold Voltage	VDPDM_IH		0.9	1	1.1	V
			1.9	2	2.1	
DP/DM Input-Low Threshold Voltage	VDPDM_IL		0.86	0.955	1.05	V
			1.86	1.96	2.06	
DP/DM Input Comparator Debounce Time	tDPDM_I	(Note 6)	0.95	1	1.05	μs
			142.5	150	157.5	
			475	500	525	
			950	1000	1050	
DP Input-High Threshold Voltage for Cable-Attached Detection	VDP_CA		0.3	0.4	0.5	V
DP Input-Low Threshold Voltage for Cable-Detached Detection	VDP_CD		0.2	0.3	0.4	V
DP Cable-Attached/Detached Detection Deglitch Time	tDP_CD		0.25	0.5	0.75	ms
			0.75	1	1.25	
			1.75	2	2.25	
			3.75	4	4.25	
DP/DM Threshold Voltage for Overvoltage Protection	VDPDM_OVP		5.75	6	6.25	V
DP/DM Overvoltage Protection Deglitch Time	tDPDM_OVP	(Note 6)	0.09	0.1	0.11	ms
GPIO Section						
GPIO Sourcing Current	IGPIO_BIAS	VDD > 3V (For high bias current application)	18	20	22	μA
			95	100	105	
GPIO Sourcing Current Clamping Voltage	VGPIO_CLP	VDD = 5V, IGPIO1_BIAS = 95μA	3.6	4	5	V
		VDD = 5V, IGPIO1_BIAS = 0μA	--	--	5	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
GPIO Sourcing Voltage	VGPIO_SRC	VDD = 5V, ILOAD = 1mA	1.2	2.1	3	V
		VDD = 5V, ILOAD = 10μA	4	4.5	5	
GPIO Pull-Up Resistance	RGPIO_PU		1.65	3.1	4.65	kΩ
GPIO Pull-Down Resistance	RGPIO_PD		30	65	100	Ω
GPIO Pull-Down Current Capability	IGPIO_PD	(Note 6)	30	--	--	mA
GPIO Input-High Threshold Voltage	VGPIO_IH		0.9	1	1.1	V
			1.9	2	2.1	
GPIO Input-Low Threshold Voltage	VGPIO_IL		0.86	0.955	1.05	V
			1.86	1.96	2.06	
GPIO1 Section						
GPIO1 Sourcing Current	IGPIO1_BIAS	VDD > 3V (For high bias current application)	18	20	22	μA
			95	100	105	
			850	1100	1350	
GPIO1 Sourcing Current Clamping Voltage	VGPIO1_CLP	VDD = 5V, IGPIO1_BIAS = 850μA	1.4	2.6	3.8	V
		VDD = 5V, IGPIO1_BIAS = 0μA	--	--	5	
Accuracy Section						
Thermal Sensor Error	ETS	25°C to 105°C (Note 6)	-7	--	7	°C

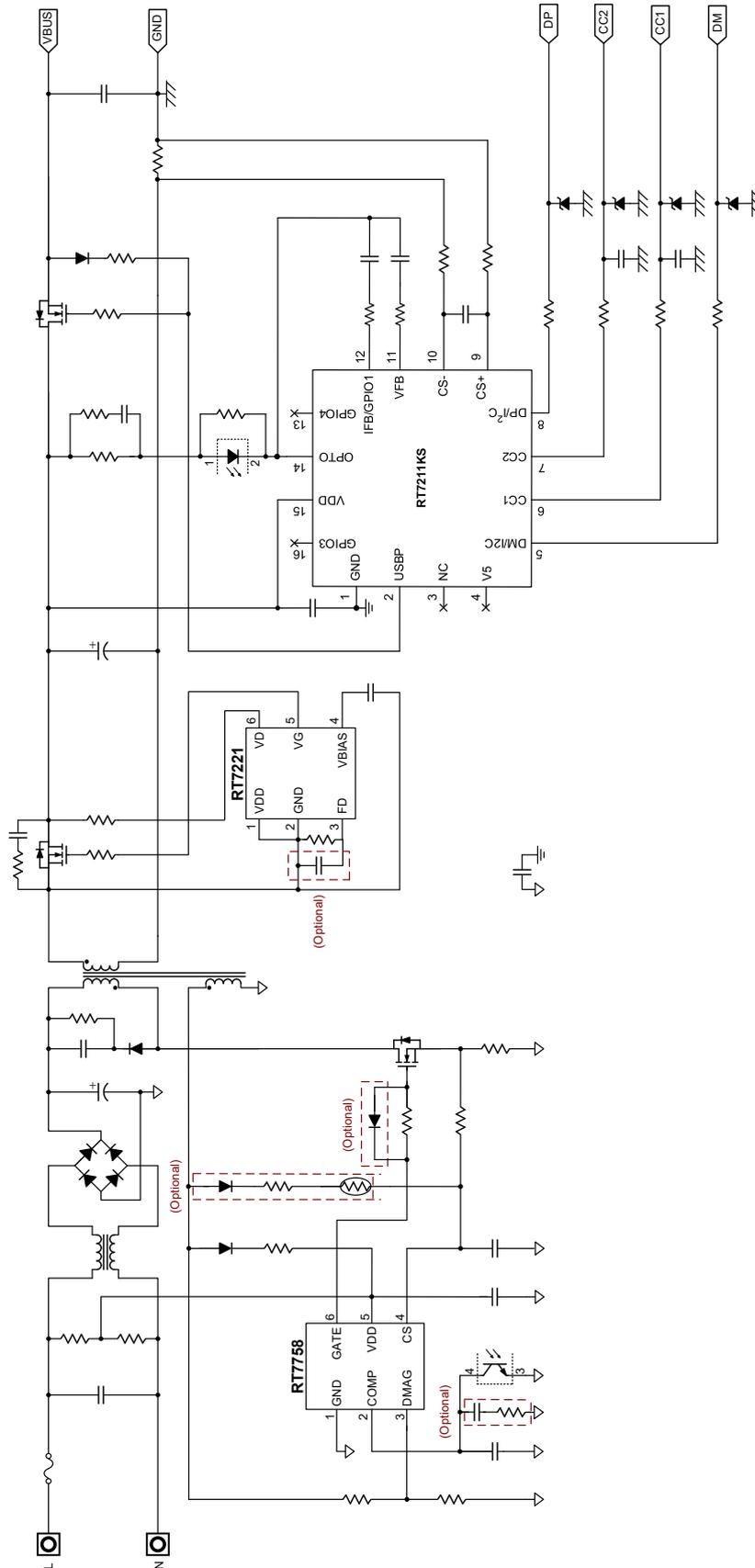
Note 6. Guaranteed by design.

13 Typical Application Circuit

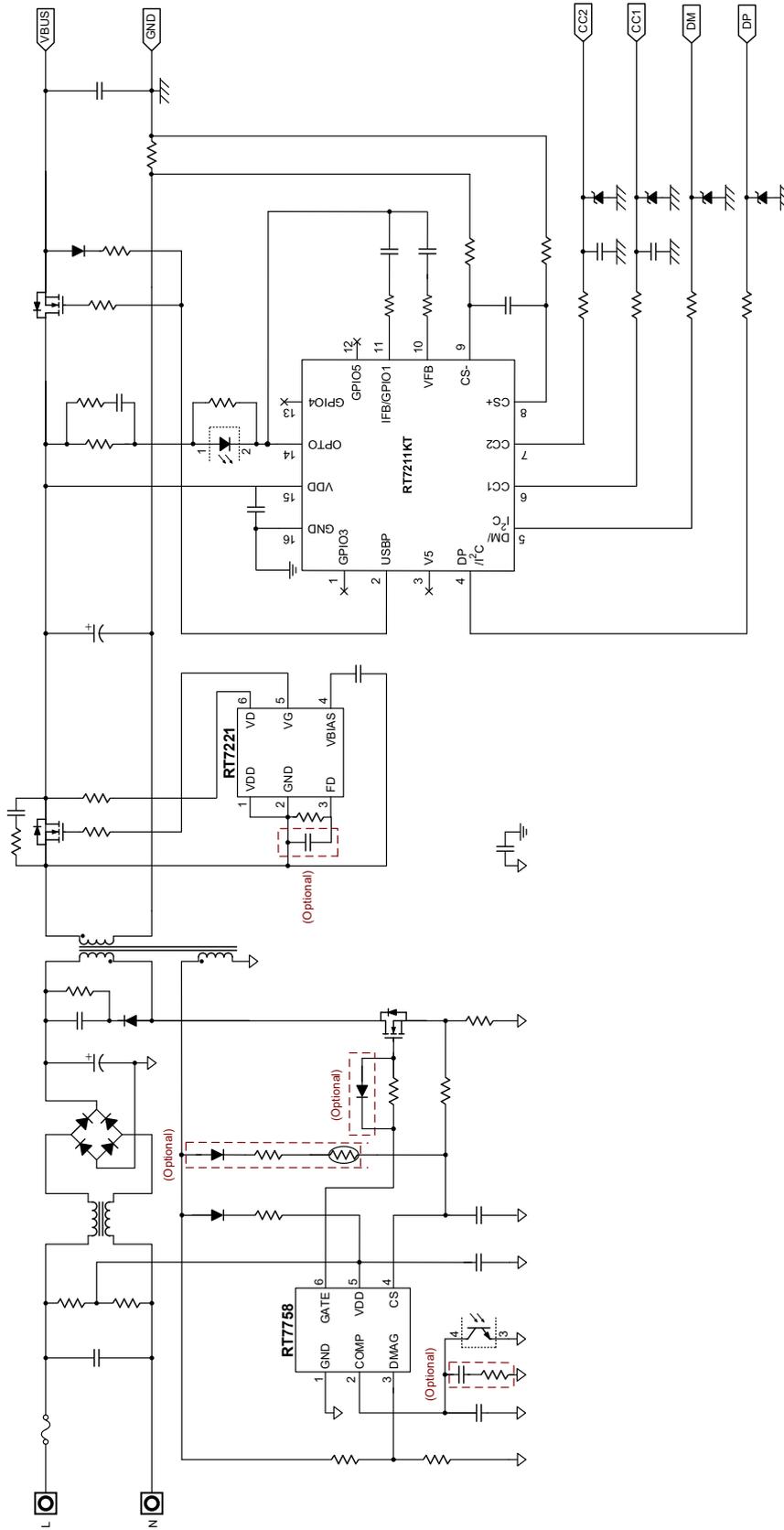
13.1 The RT7211KS Typical Application Circuit for Sink Side



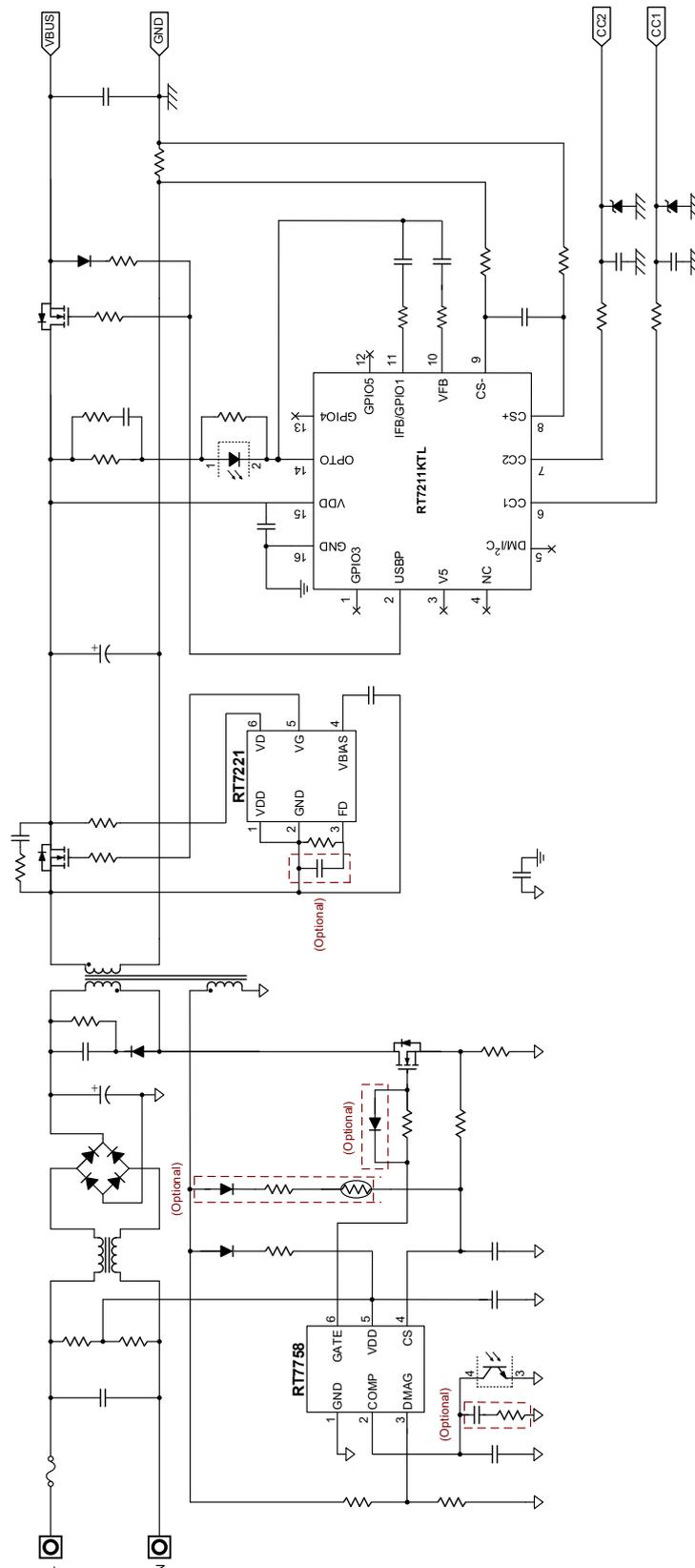
13.2 The RT7211KS Typical Application Circuit for Source Side



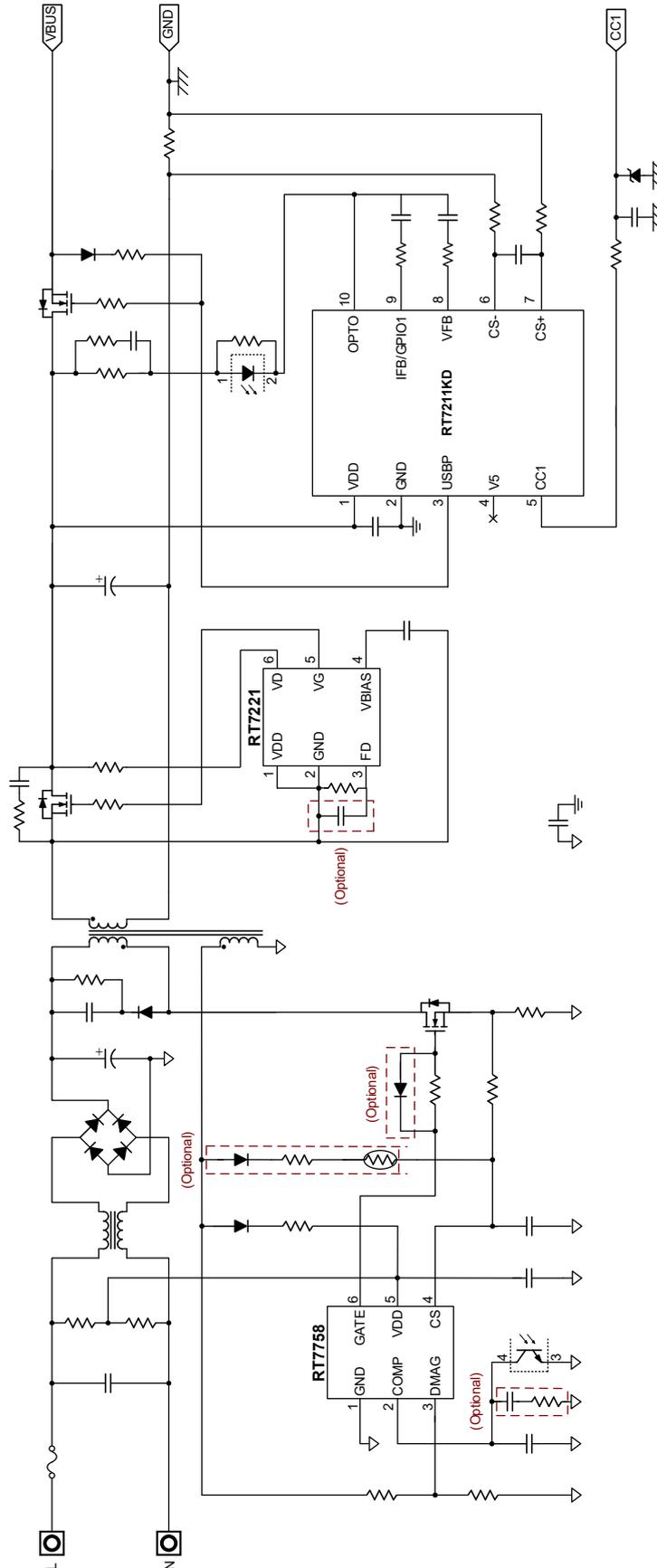
13.3 The RT7211KT Typical Application Circuit for Source Side



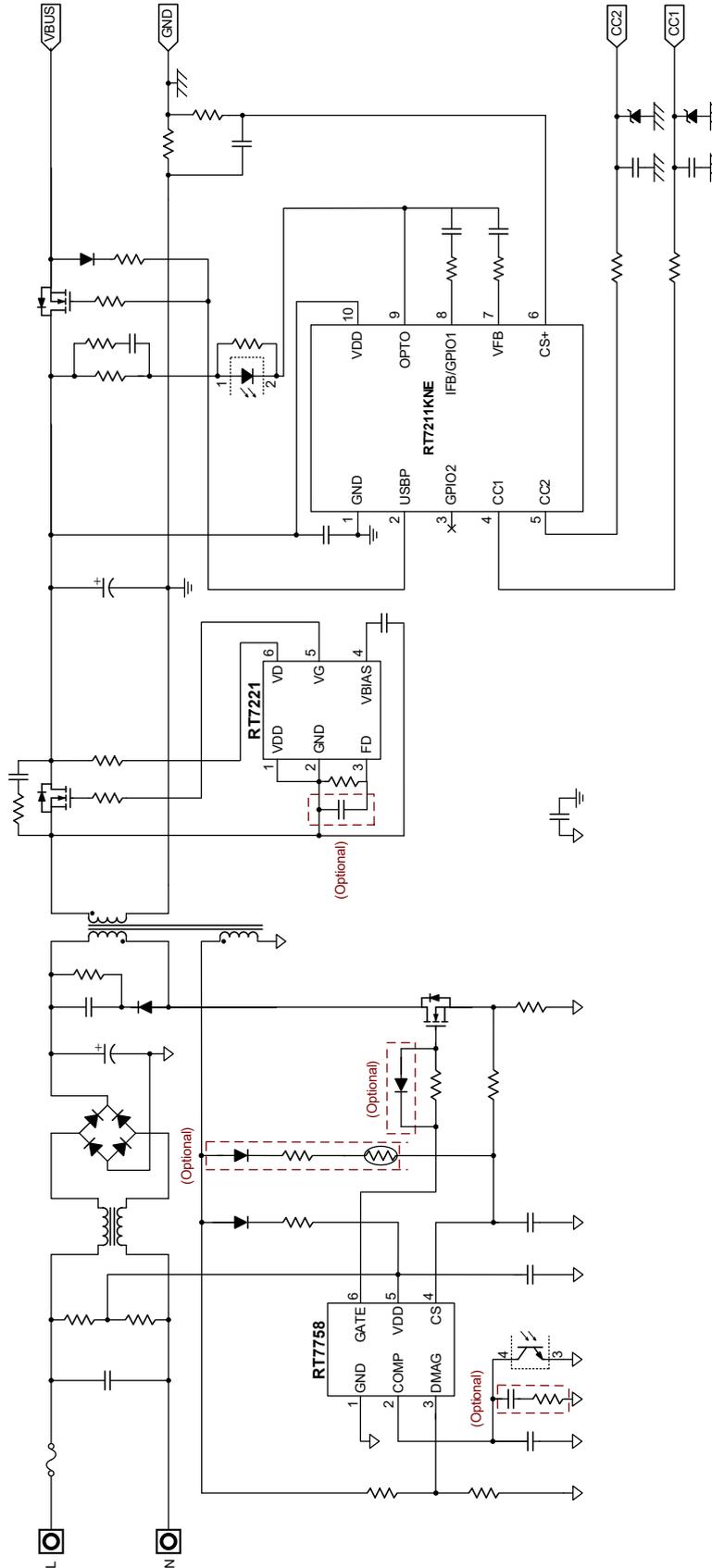
13.4 The RT7211KTL Typical Application Circuit for Source Side



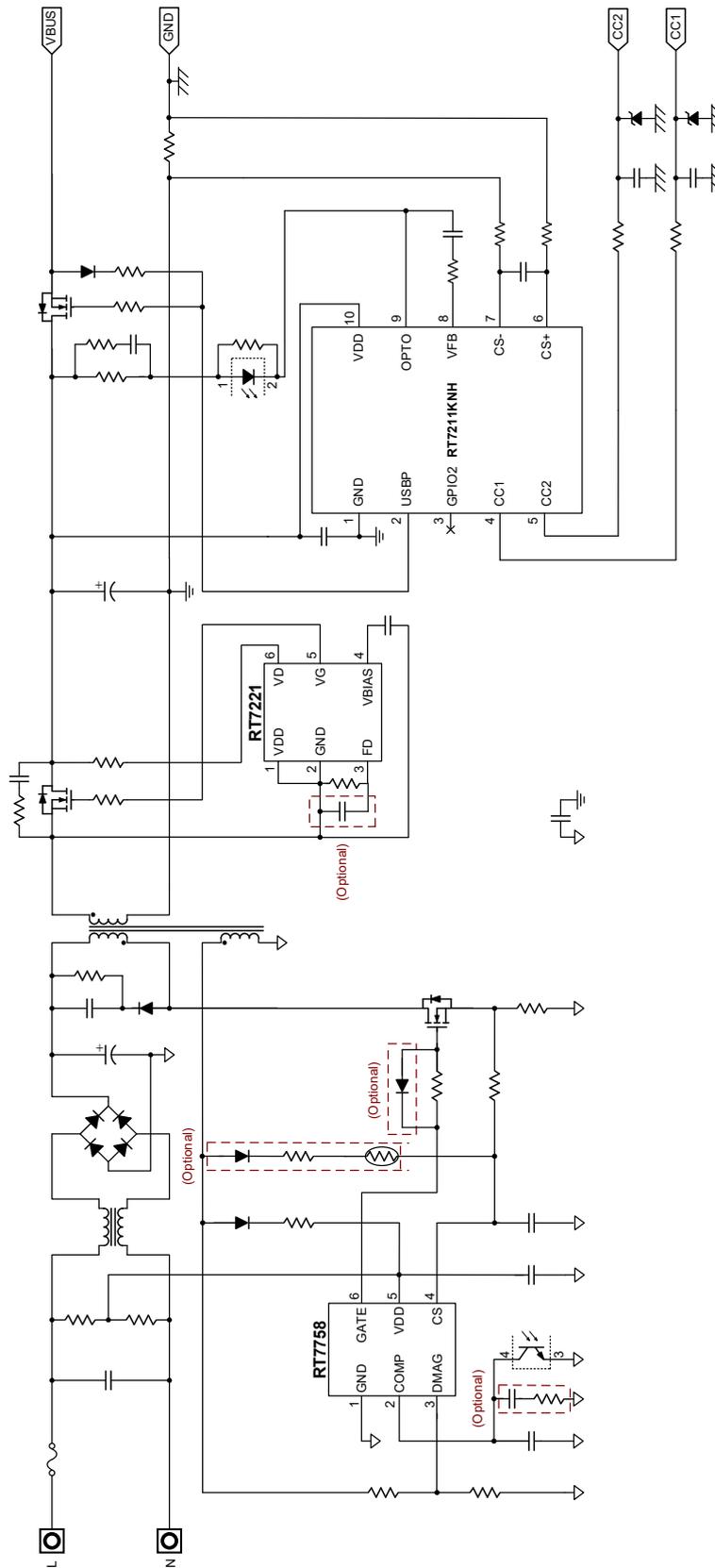
13.5 The RT7211KD Typical Application Circuit for Source Side



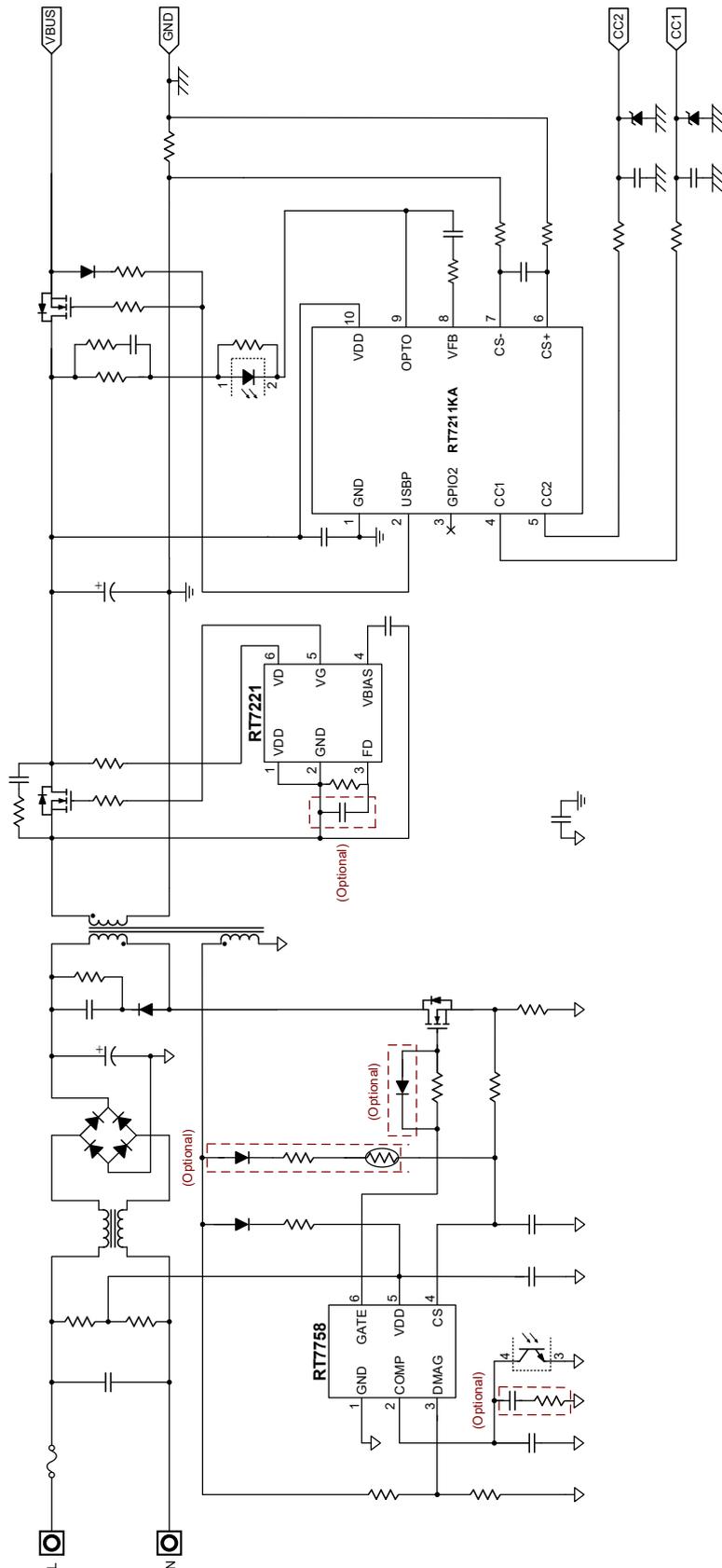
13.6 The RT7211KNE Typical Application Circuit for Source Side



13.7 The RT7211KNH Typical Application Circuit for Source Side

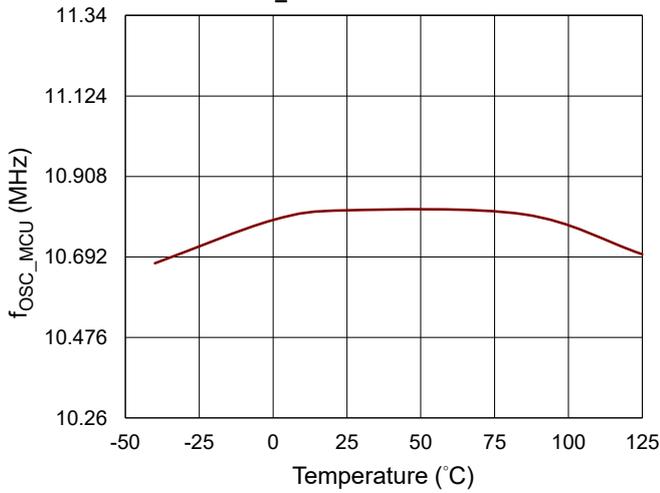


13.8 The RT7211KA Typical Application Circuit for Source Side

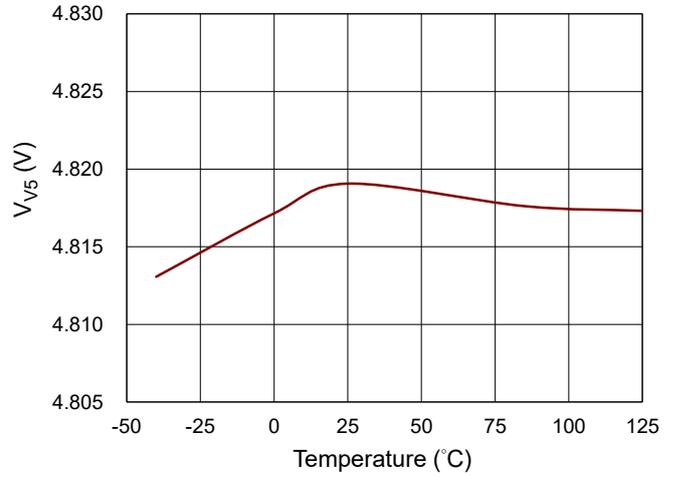


14 Typical Operating Characteristics

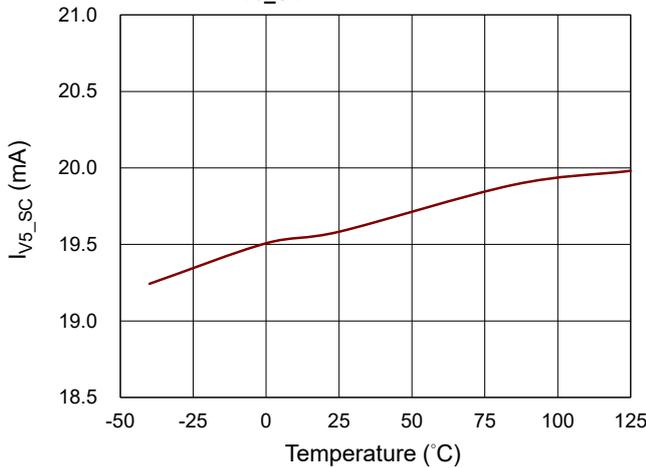
f_{OSC_MCU} vs. Temperature



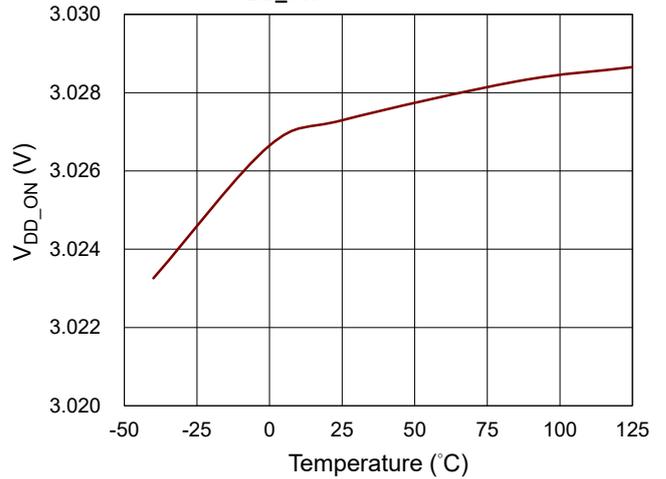
V_{V5} vs. Temperature



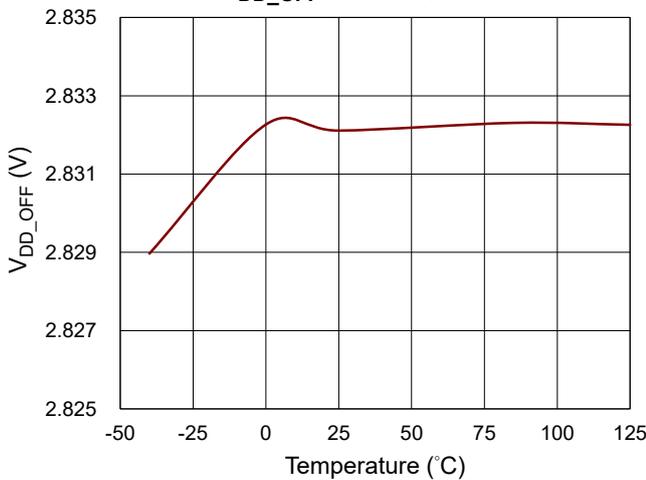
I_{V5_SC} vs. Temperature



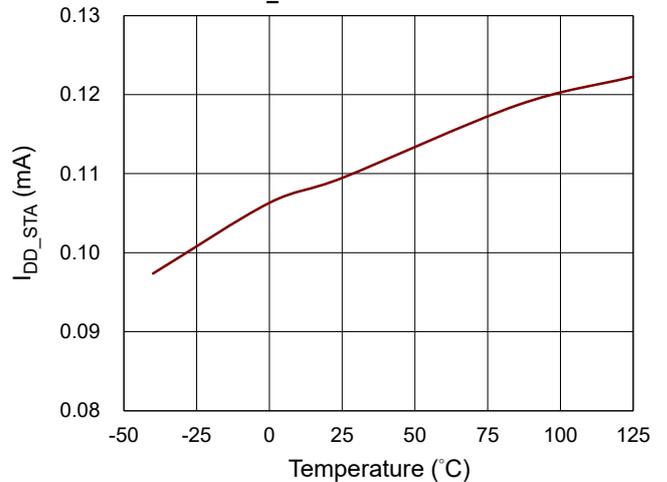
V_{DD_ON} vs. Temperature

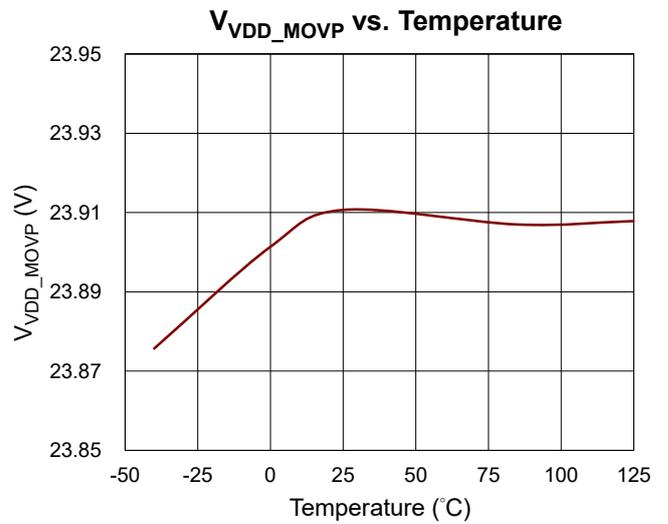
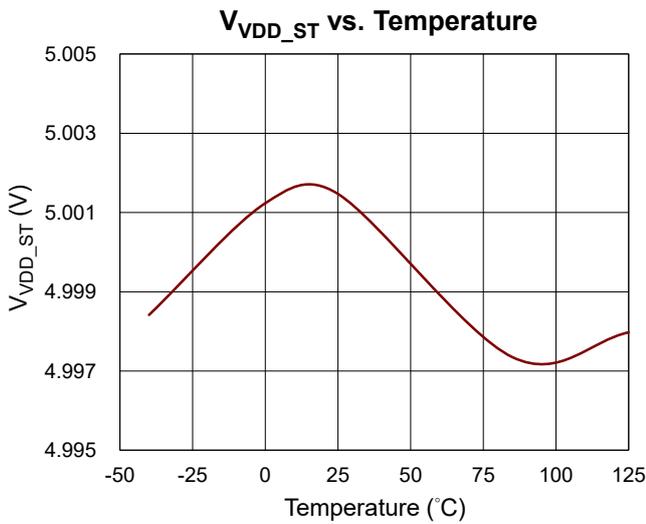
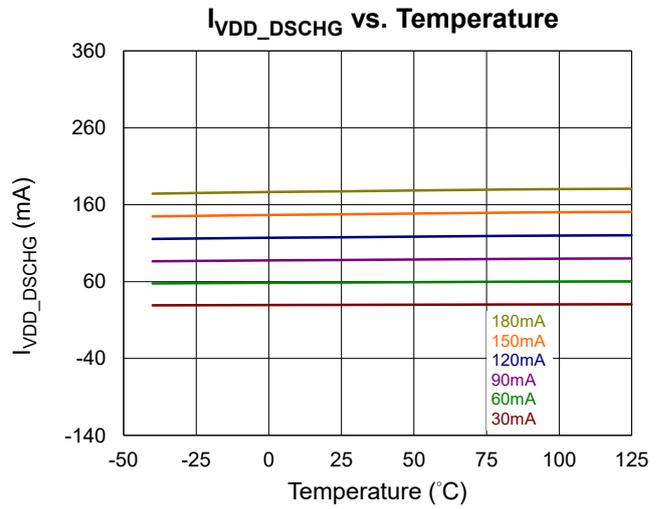
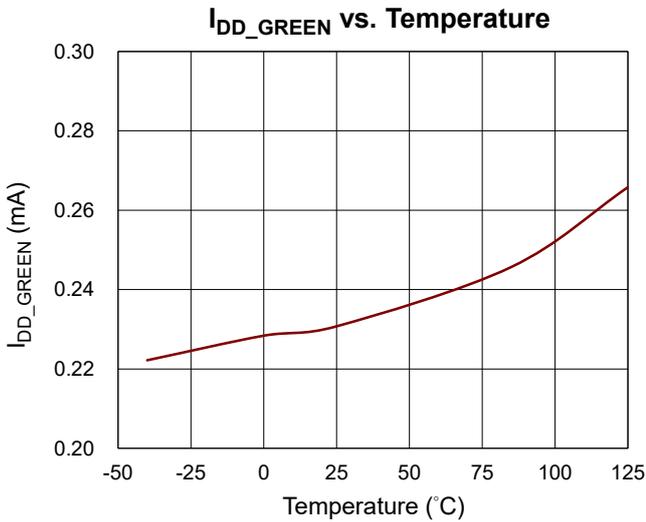
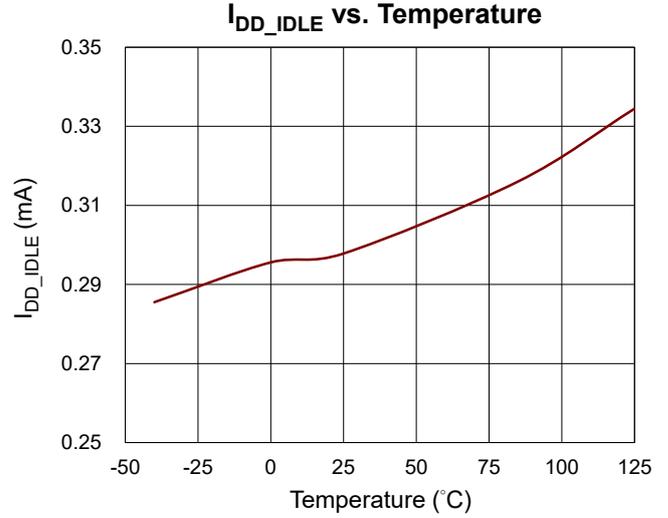
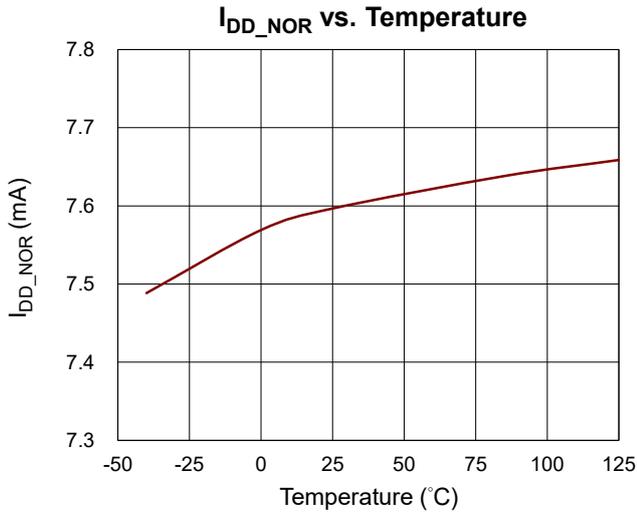


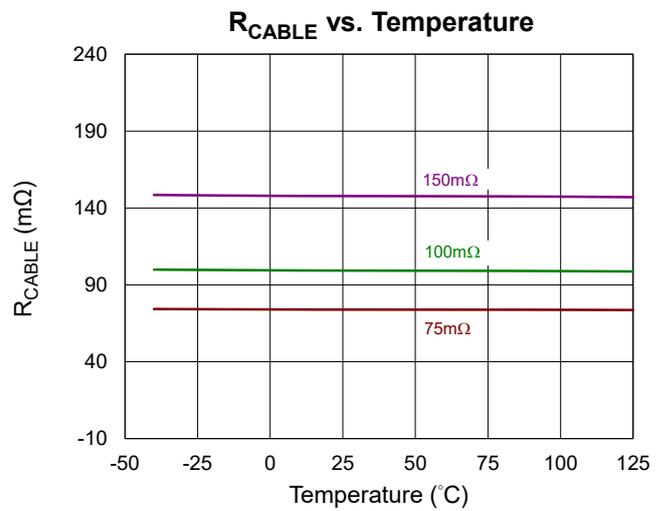
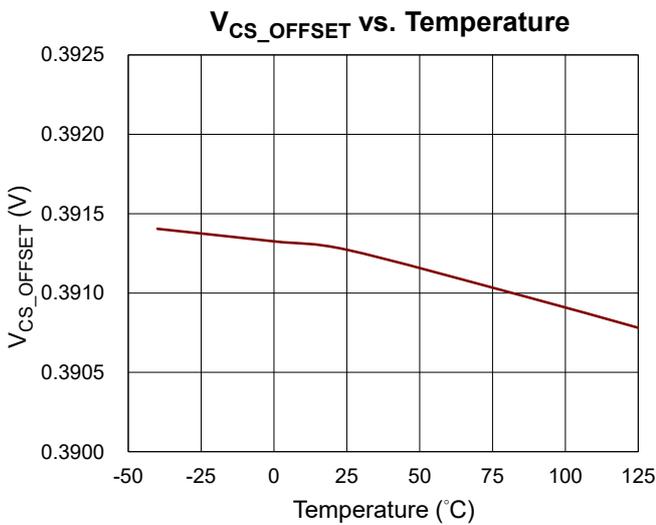
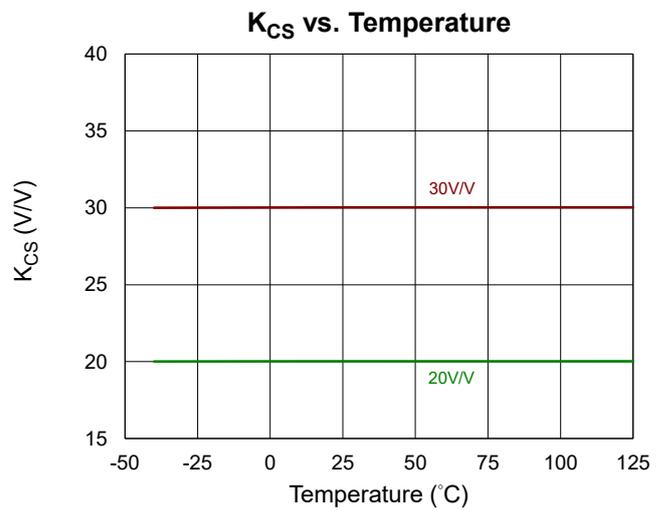
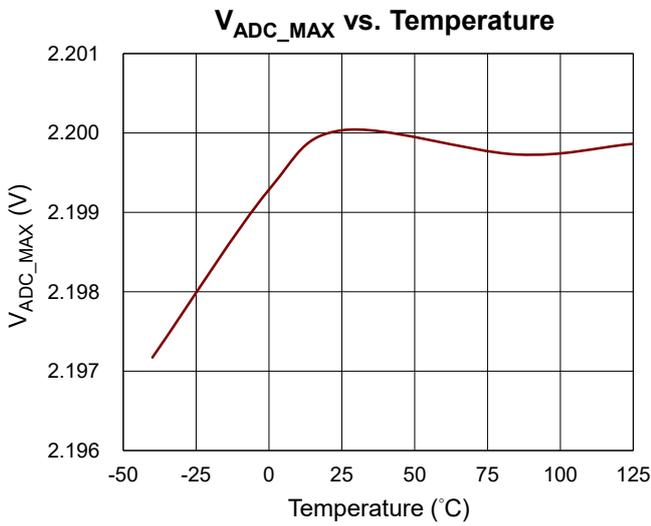
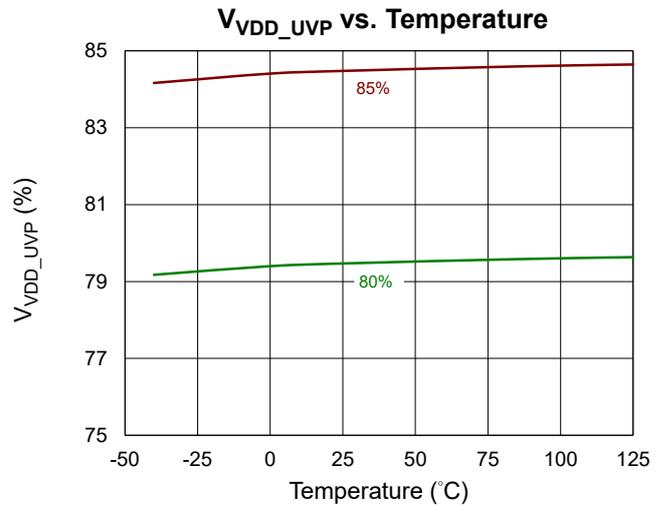
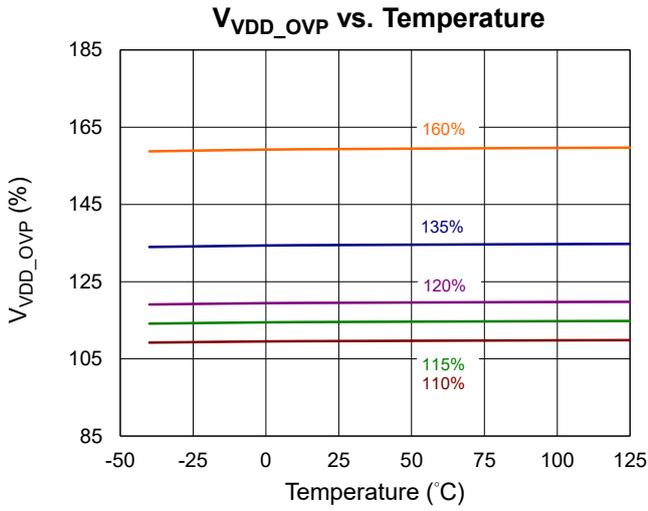
V_{DD_OFF} vs. Temperature

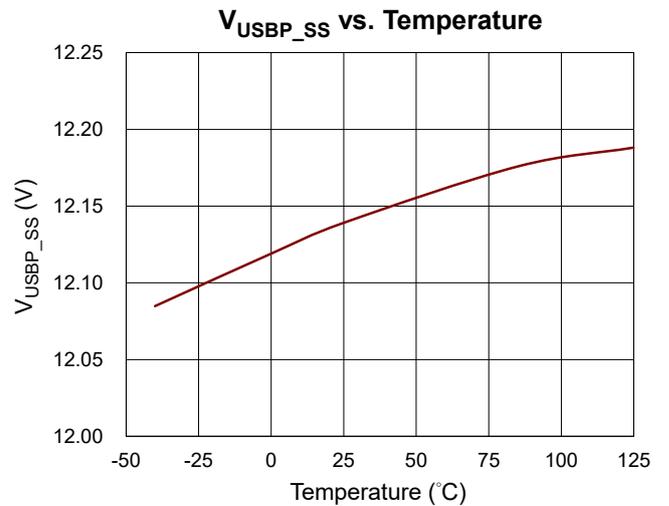
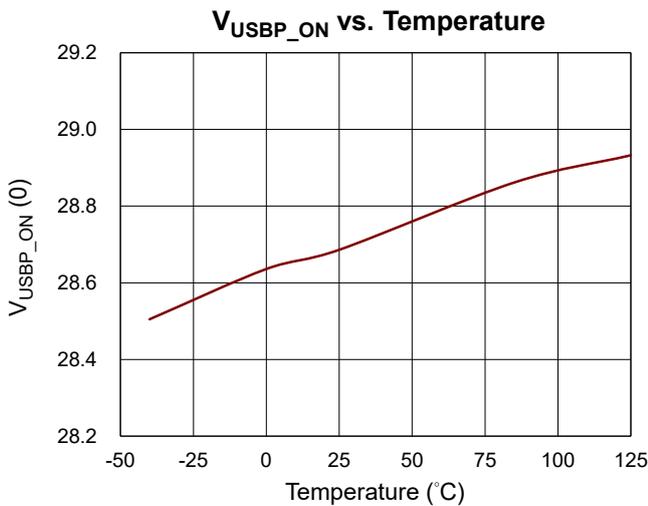
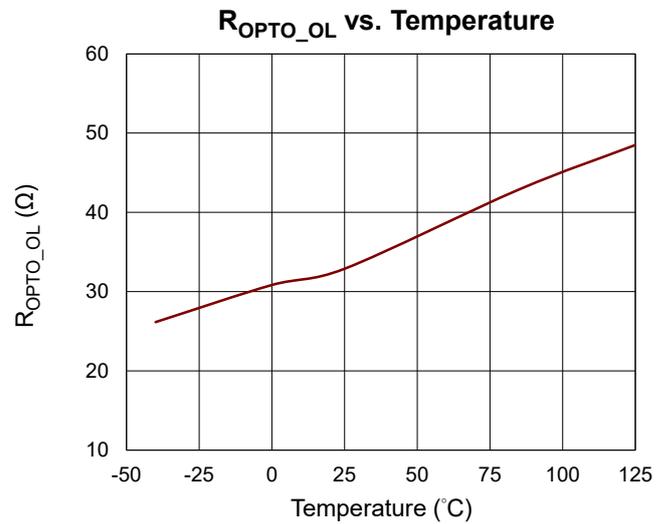
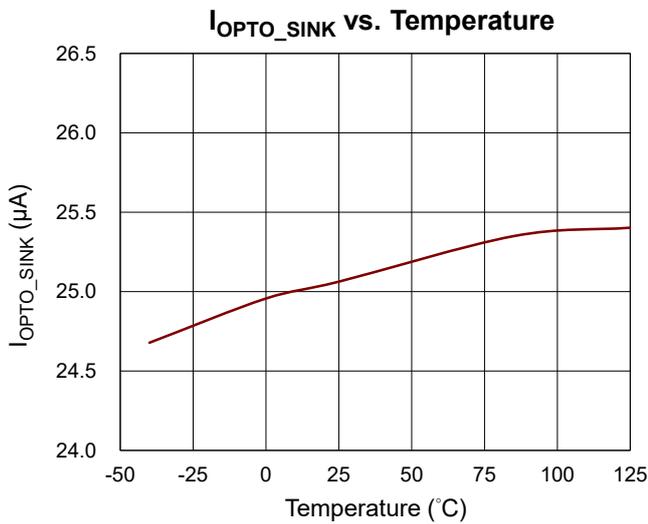
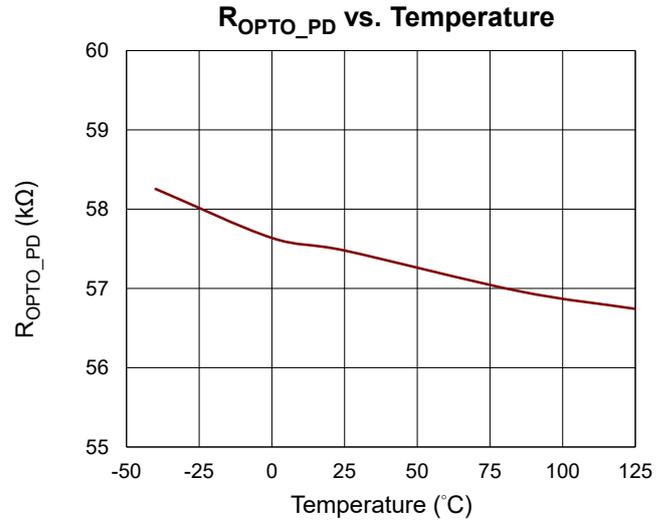
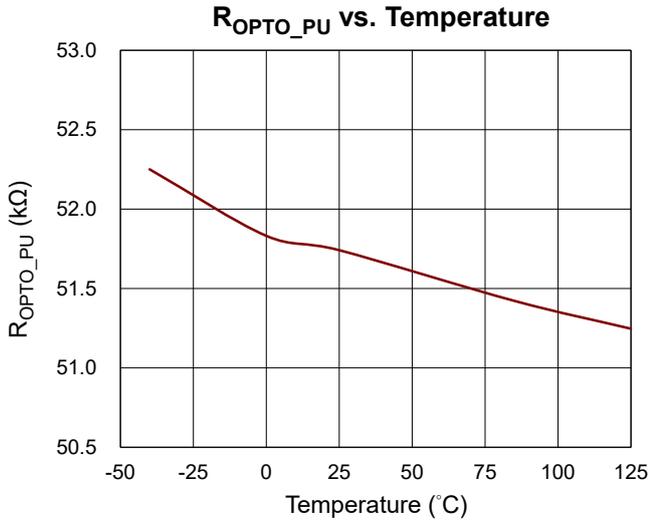


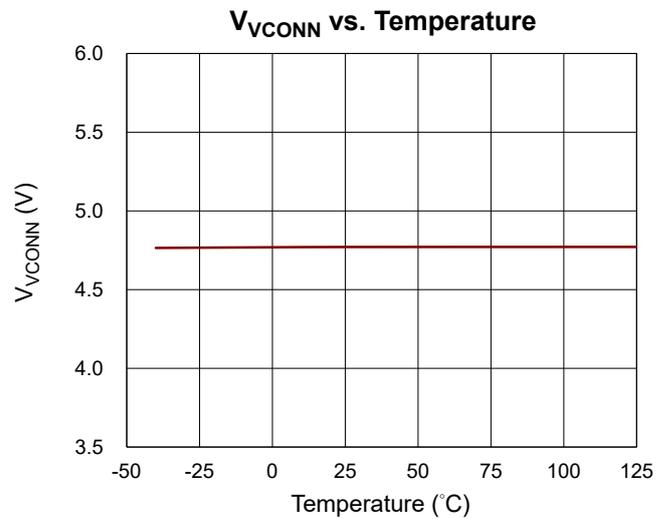
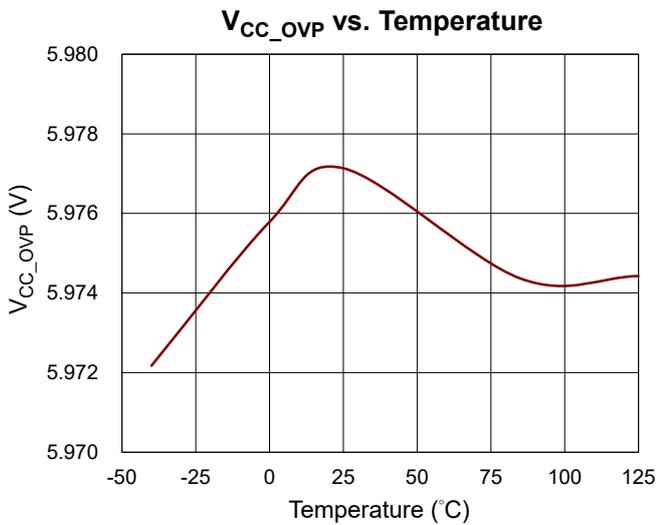
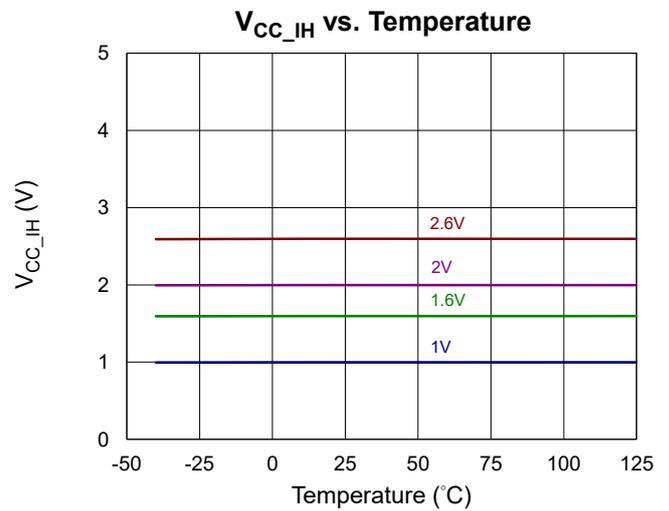
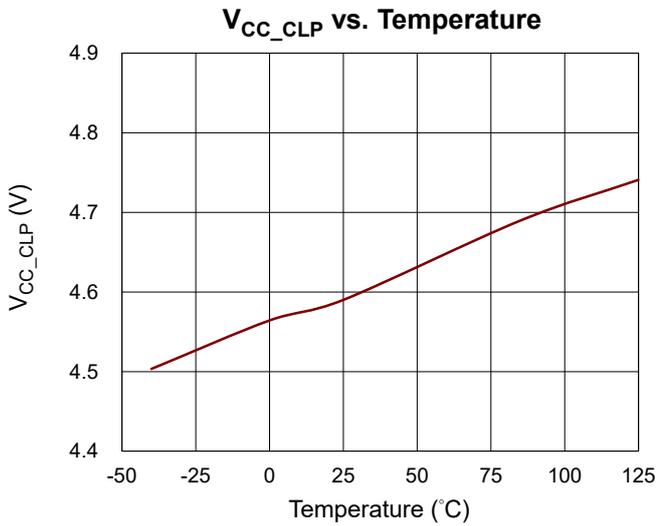
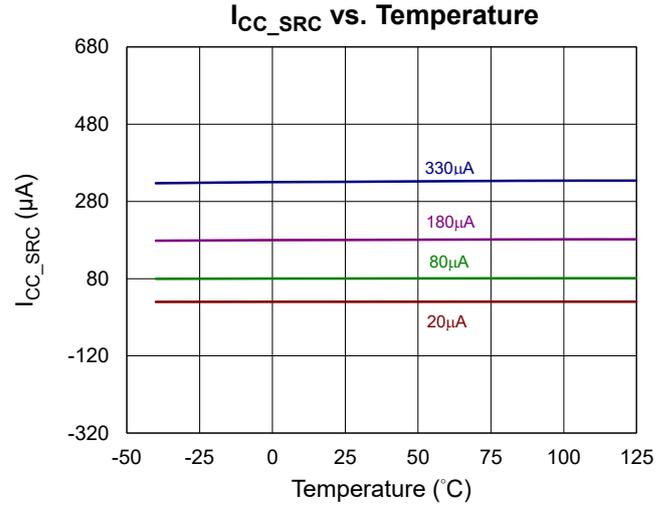
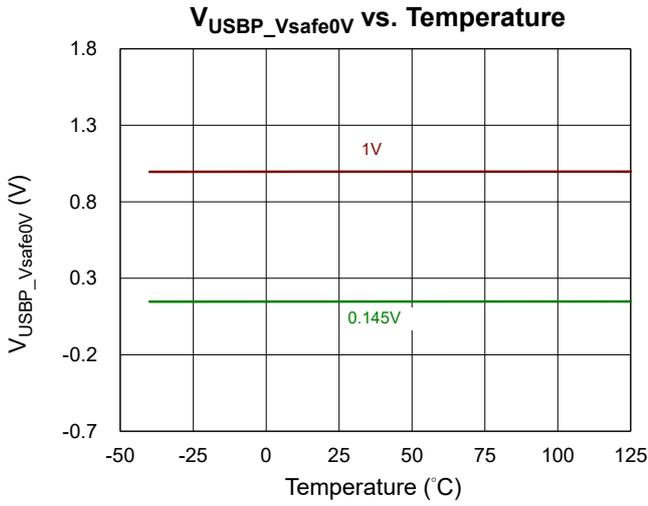
I_{DD_STA} vs. Temperature



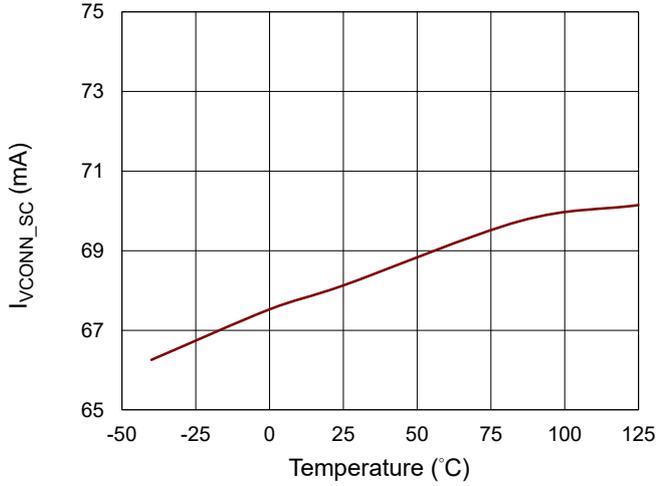




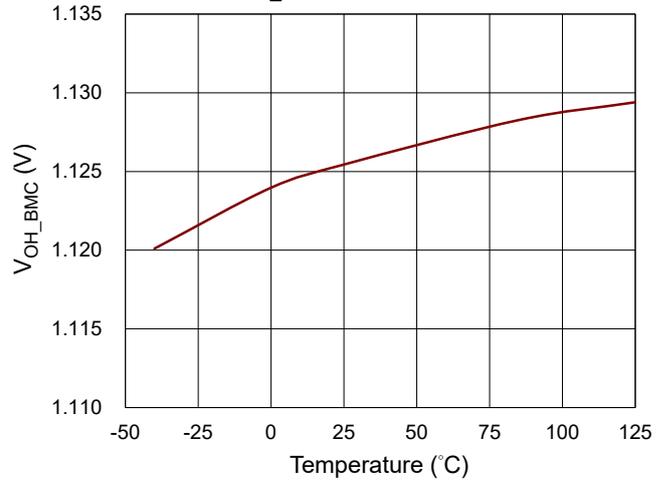




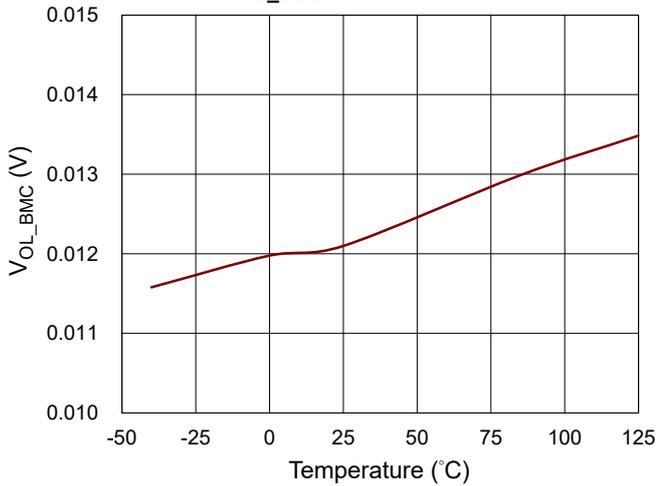
I_{VCONN_SC} vs. Temperature



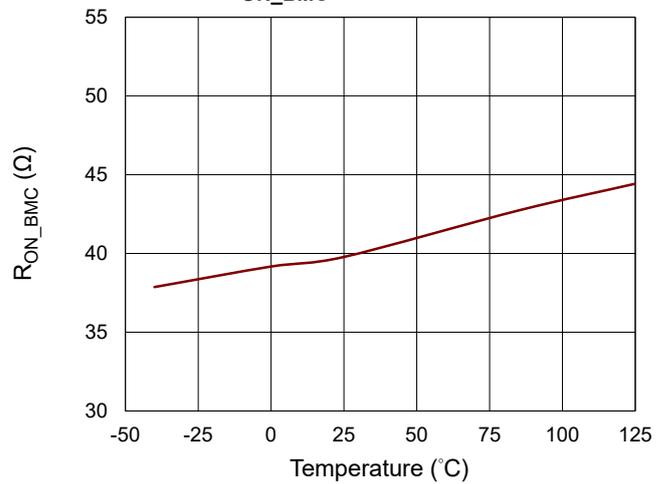
V_{OH_BMC} vs. Temperature



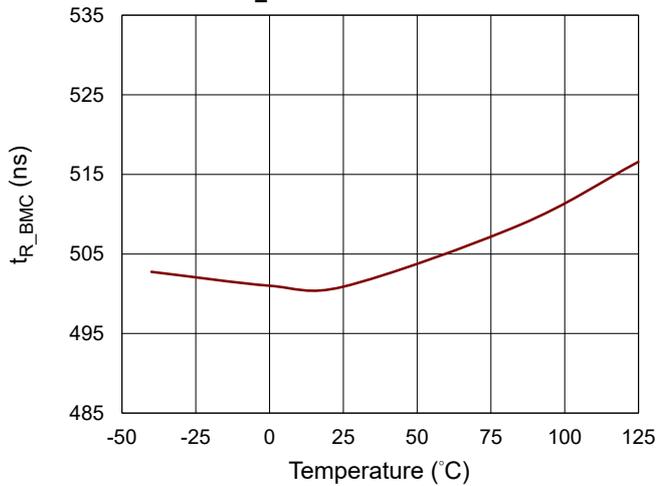
V_{OL_BMC} vs. Temperature



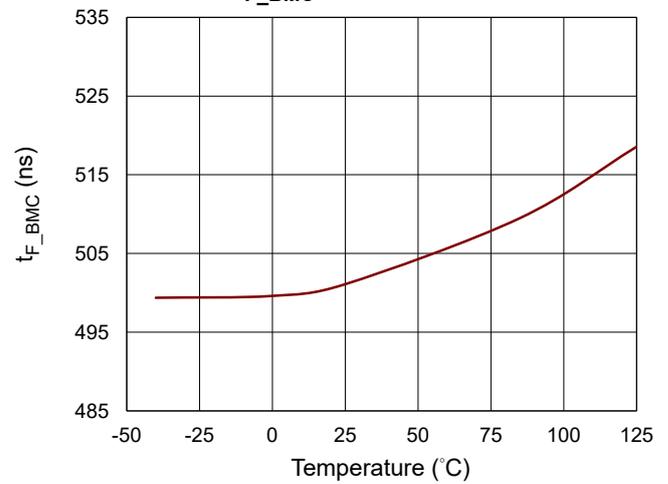
R_{ON_BMC} vs. Temperature

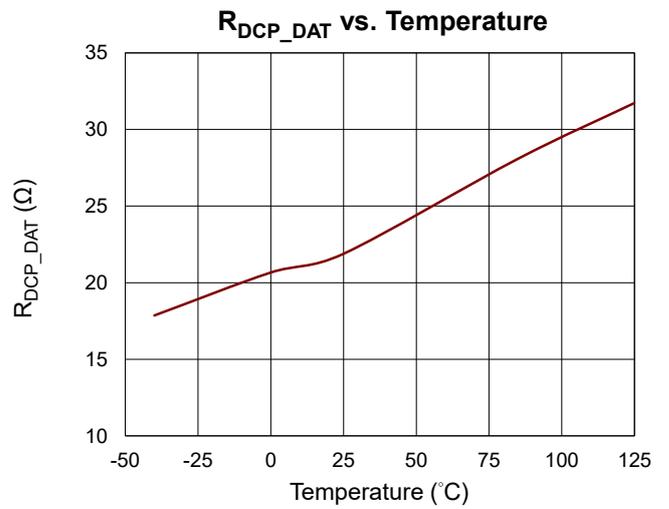
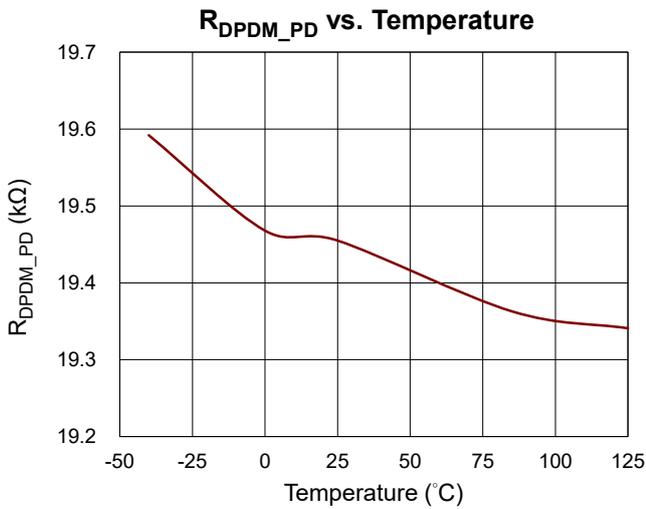
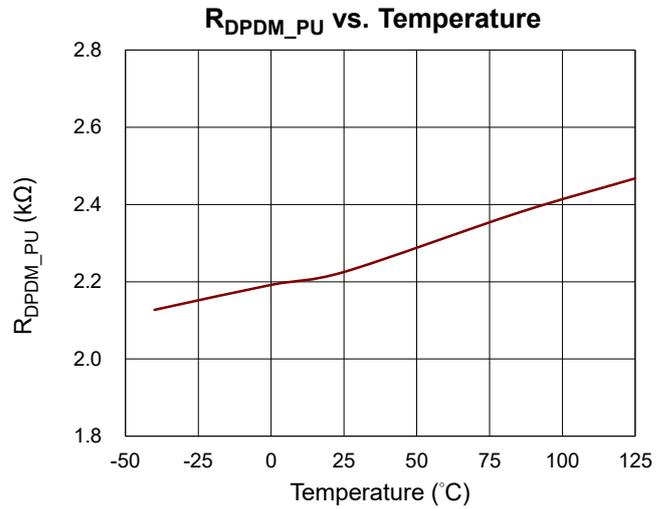
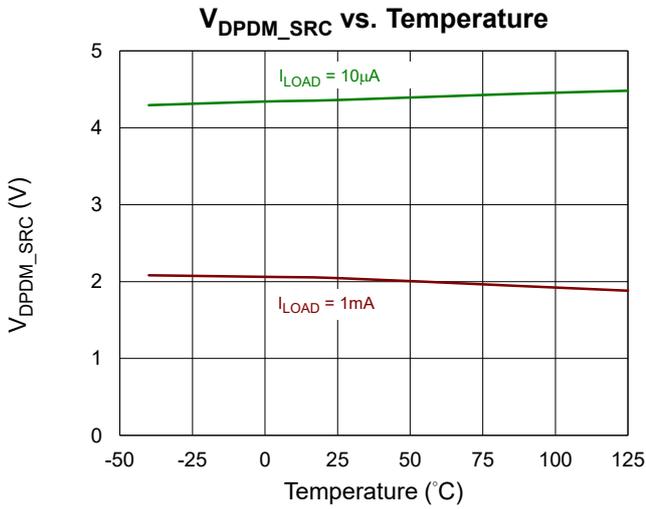
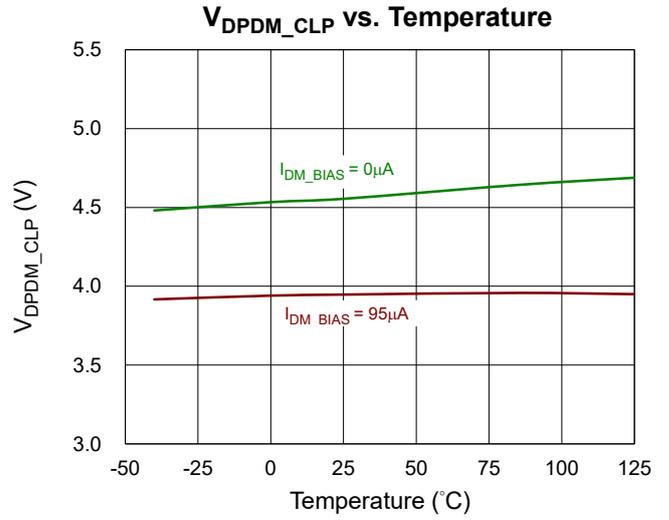
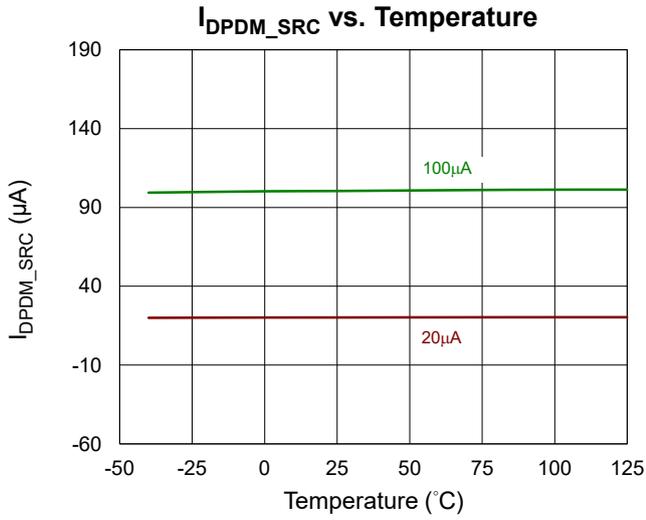


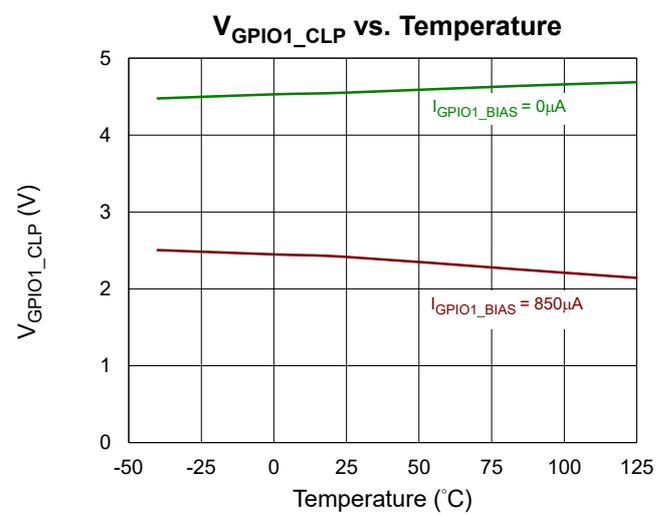
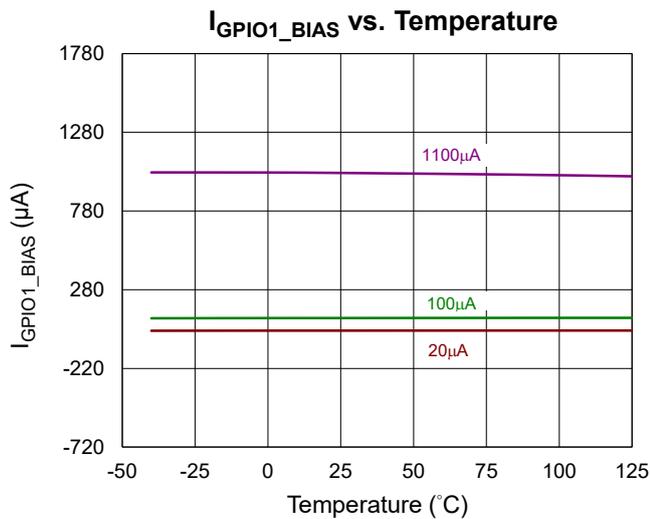
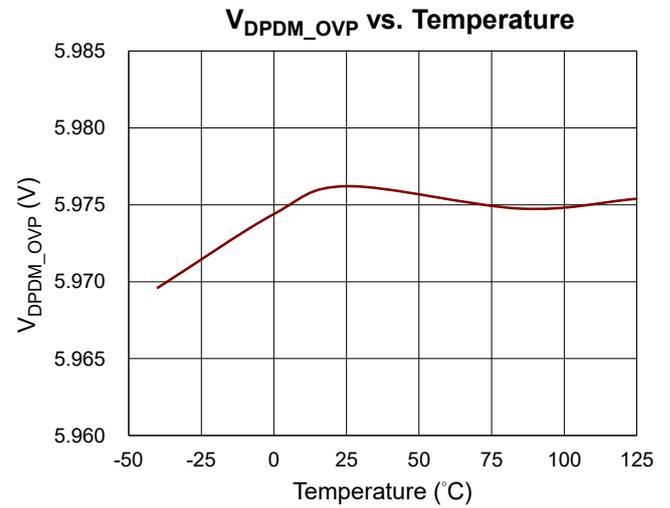
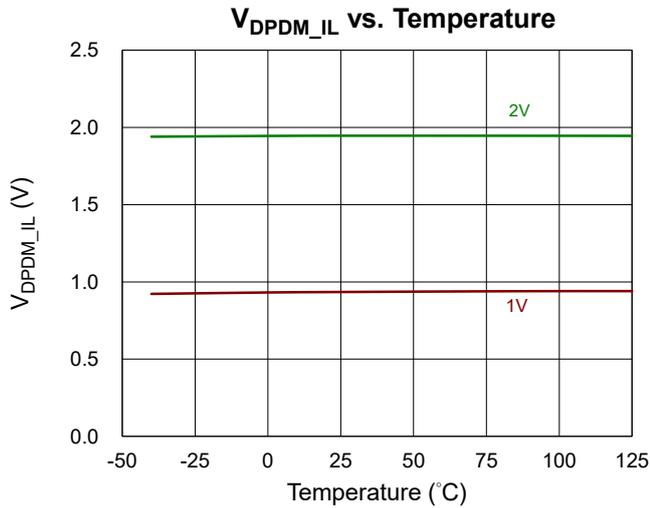
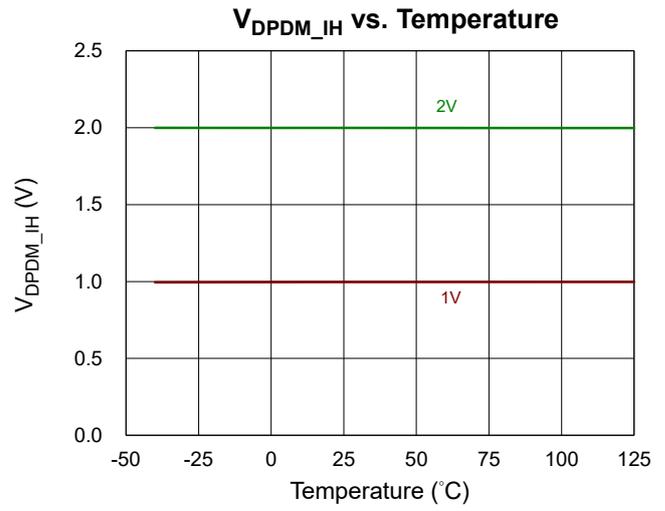
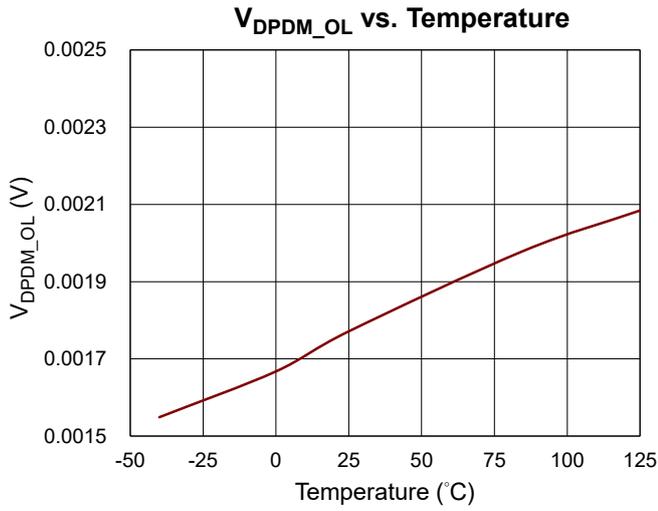
t_{R_BMC} vs. Temperature



t_{F_BMC} vs. Temperature







15 Operation

A highly integrated secondary-side programmable controller offering versatile functions and comprehensive protections for off-line AC-DC converters.

15.1 Power Structure

Two internally regulated voltages, V5 and V2, are derived from the VDD supply. V5 powers the internal circuitry, while V2 supplies the internal microprocessor (MCU).

15.2 Constant Voltage and Constant Current (CV/CC) Shunt Regulators

Two parallel regulators are connected to the OPTO pin, which functions as an open-drain output. Each feedback loop operates like a traditional TL431 shunt regulator, but with a wider VOPTO operating voltage range from 0.3V to 25V. This allows converter designs to achieve a wider output voltage range. When VDD is below the turn-on threshold (V_{VDD_ON}), the OPTO pin remains in a high-impedance state to ensure a smooth power-on sequence. The reference voltages for the voltage and current feedback loops (V_{DAC_CV} and V_{DAC_CC}) are generated by the analog outputs of dedicated DACs. An 11-bit DAC is used for voltage, while a 10-bit DAC is used for current. This enables high-precision CV and CC regulation.

15.2.1 Constant Voltage (CV) Loop

V_{DAC_CV}, the analog output from the DAC controlled by the MCU, sets the output voltage, which is determined by the following equation:

$$V_{OUT} = K_{FB} \times V_{DAC_CV}$$

where

$$K_{FB} = (R_{FB1} + R_{FB2}) / R_{FB2} = 10$$

15.2.2 Hardware Cable Compensation

A compensation current proportional to the load current is applied to the VFB pin to compensate for the voltage drop across the cable resistance. The user can select the compensation setting (R_{CABLE}) according to the actual cable resistance. For example, if the cable resistance is 100 mΩ, it is recommended to select the 100 mΩ setting.

15.2.3 Constant Current (CC) Loop

V_{DAC_CC}, the analog output from the DAC controlled by the MCU, sets the output current, which is determined by the following equation:

$$I_{OUT} = (V_{DAC_CC} - V_{CS_OFFSET}) / K_{CS} / R_{CS}$$

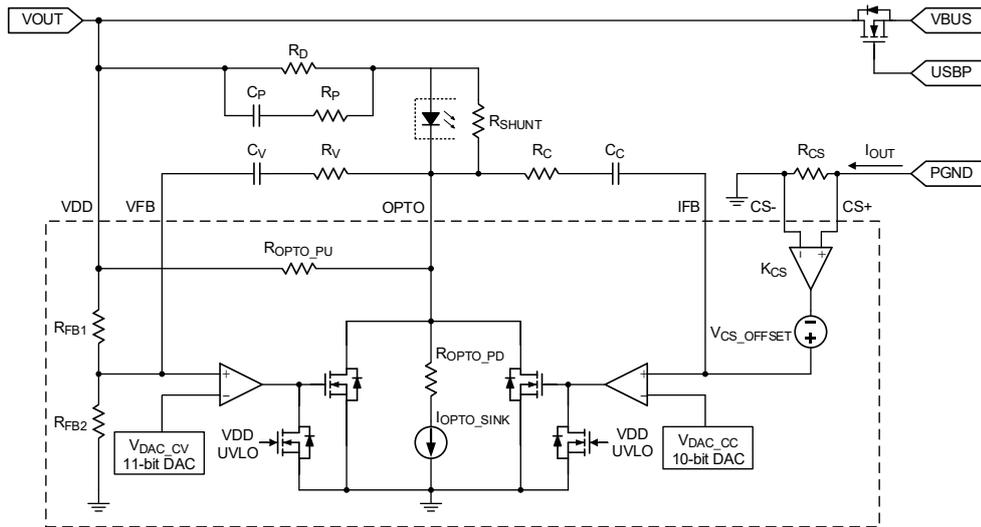


Figure 1. CV and CC Loops

15.3 N-MOSFET Driver

The charge pump drives the integrated blocking N-MOSFET. The soft-start function is implemented using an 8-bit DAC to prevent voltage droop during startup conditions with capacitive loads.

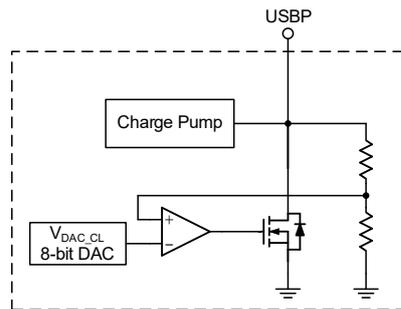


Figure 2. Soft-Start Function

15.4 Discharge

15.4.1 VDD Pin Discharger for Output Capacitor

The VDD pin provides discharge current control, acting as a bleeder to discharge the output capacitor when a device is detached or when a lower output voltage is requested, such as reducing VOUT from 20V to 5V. The I_VDD_DISCHG capability should consider both the operating voltage and output capacitance. The discharge current is programmable via the internal register based on power dissipation.

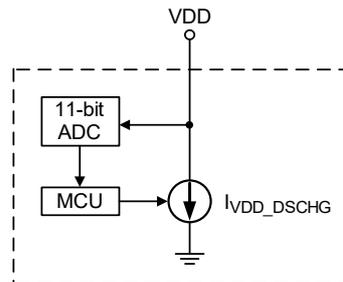


Figure 3. Discharge Current Control of the VDD Pin

15.4.2 USBP Pin or GPIO Pin Discharger for Vsafe0V

Vsafe0V discharge can be implemented using either the USBP pin or a GPIO pin. The USBP pin, combined with an open-drain driver and hardware comparator, automatically turns off the open-drain pull-low MOSFET when the external voltage drops below the Vsafe0V specification, saving one GPIO pin.

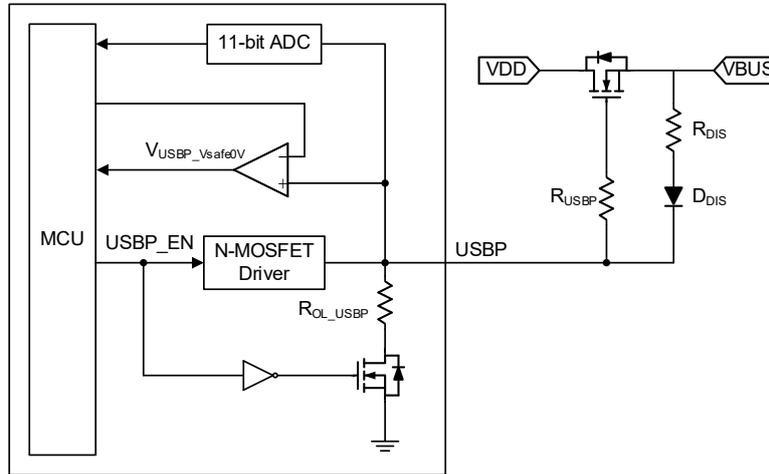


Figure 4. Open-Drain Driver of the USBP Pin

Alternatively, a GPIO pin can be used for discharge, with the voltage continuously monitored by the ADC to ensure compliance with the Vsafe0V specification.

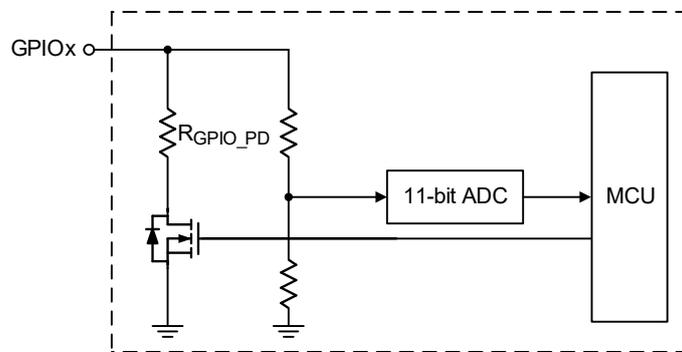


Figure 5. Open-Drain Driver of the GPIO Pin

15.5 DP, DM and GPIO Pins Functional Description

The DP, DM, and GPIO pins support multiple functions, including general-purpose input and open-drain output. They can also be configured as current or voltage sources, and serve as ADC inputs for voltage monitoring. A hardware comparator enables voltage change detection and allows the device to wake up from power-saving mode.

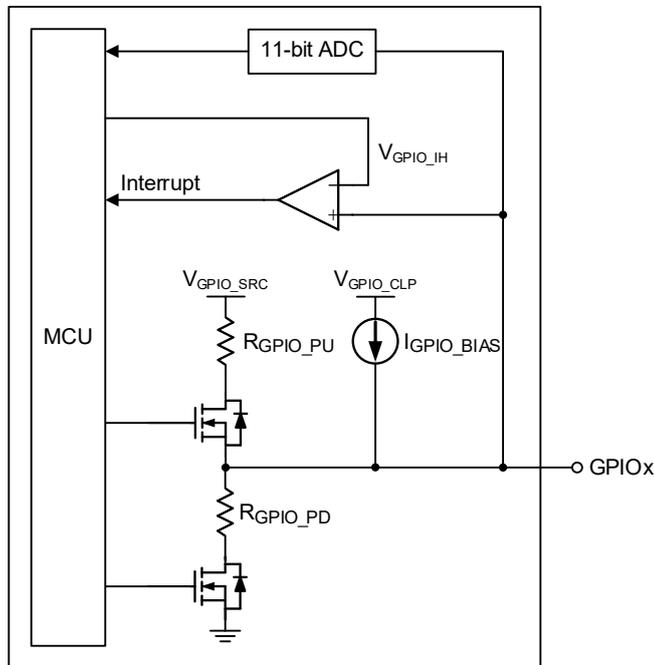


Figure 6. Internal Circuit Diagram of the DP, DM, and GPIO Pins

15.6 CC1 and CC2 Pins Functional Description

15.6.1 CC Pin Attach/Detach Detection

The CC pin supports attach/detach detection and current advertisement in accordance with the USB Type-C specification. Hardware comparators detect attach and detach events by instantly responding to voltage changes on the CC pin, allowing the system to quickly identify cable insertion or removal.

15.6.2 PD PHY

The USB PD PHY implements a BMC transceiver for communication over the CC channel. It supports packet encoding and decoding, CRC generation and checking, SOP/EOP detection, and clock recovery, ensuring robust and reliable data exchange between the protocol layer and the CC line.

15.6.3 VCONN

The device integrates a VCONN switch to supply power (up to 100mW) to active or electronically marked (e-marked) cables through the unused CC pin. The VCONN path features overcurrent protection to ensure safe operation.

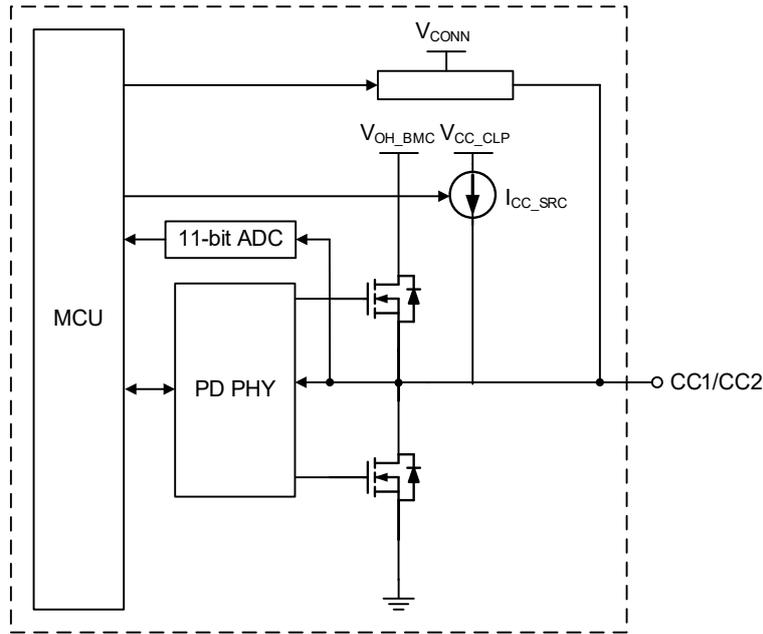


Figure 7. Internal Circuit Diagram of the CC1 and CC2 Pins

15.7 Temperature Sensing

15.7.1 Internal

A built-in temperature sensor supports temperature reporting and provides over-temperature protection (OTP).

15.7.2 External

The current source of the CC1, CC2, DP, DM, and GPIO pins can source current to a thermistor, enabling the ADC to measure the resulting voltage. Temperature is calculated by converting this value according to the thermistor's characteristic table, supporting temperature reporting and over-temperature protection (OTP).

16 Application Information

(Note 7)

16.1 VDD Adaptive Overvoltage Protection

A fast turn-off blocking N-MOSFET provides VOUT overvoltage protection. When the internal voltage related to VDD exceeds the programmable threshold (V_{VDD_OVP}), the blocking N-MOSFET is immediately turned off and a fault flag is sent to the embedded MCU for customized protection actions. This mechanism safeguards against malfunctions such as optocoupler aging in the feedback loop.

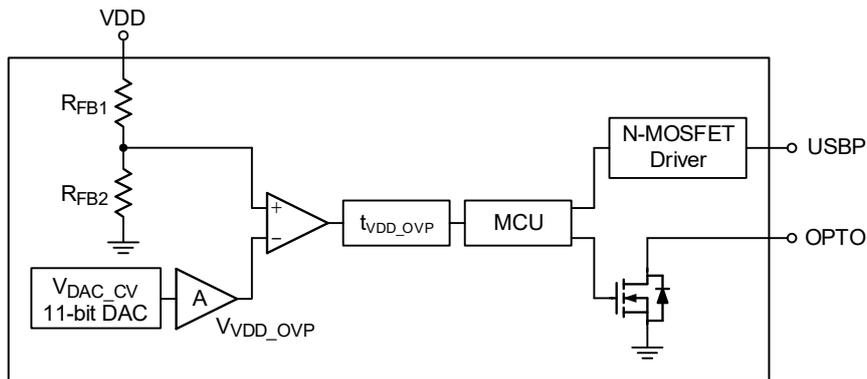


Figure 8. OVP Functional Diagram

16.2 VDD Adaptive Undervoltage Protection

A fast turn-off blocking N-MOSFET provides VOUT undervoltage protection. When the internal voltage related to VDD drops below the programmable threshold (V_{VDD_UVP}), the blocking N-MOSFET is immediately turned off and a fault flag is sent to the embedded MCU for customized protection actions. This mechanism safeguards against feedback failure and output short-circuit events.

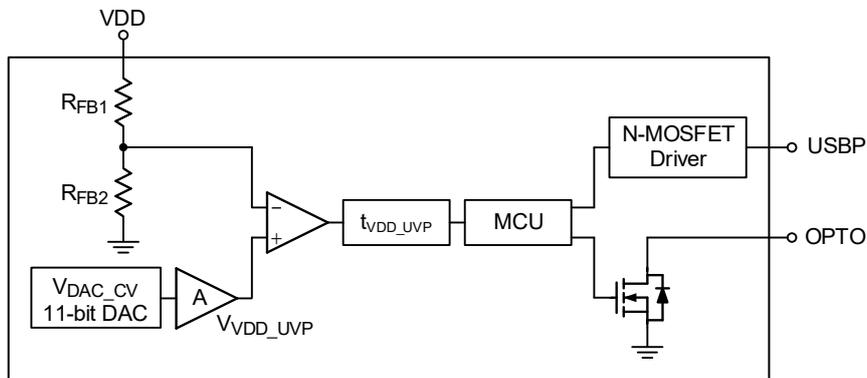


Figure 9. UVP Functional Diagram

16.3 Limited Power Source Protection

Limited Power Source (LPS) protection is implemented by monitoring both the voltage at the SR gate after voltage division and the voltage across the current sense resistor. When the divided voltage at the SR gate exceeds the firmware-defined voltage threshold, but the current sense voltage remains below the firmware-defined value, this indicates an energy mismatch between the SR gate pulse and the current sense reading. Under these conditions, LPS protection is triggered to ensure system safety.

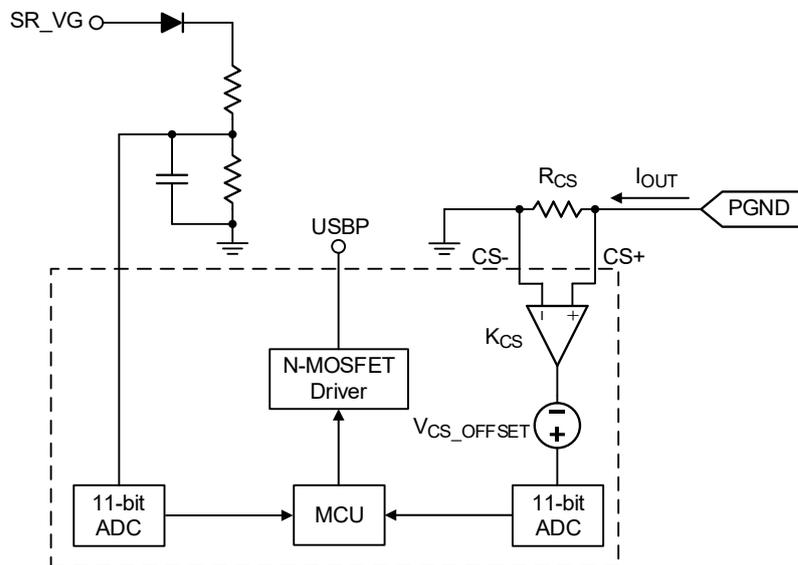


Figure 10. LPS Functional Diagram

16.4 Programmable Overcurrent Protection

Programmable overcurrent protection (OCP) is achieved by amplifying the voltage across the current sense resistor, adding an offset voltage, and converting the result with the ADC for current calculation. When the measured current exceeds the user-defined protection threshold, OCP is triggered to prevent damage and ensure system reliability.

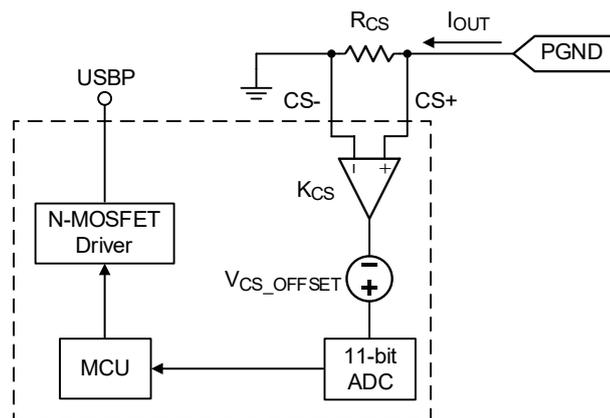


Figure 11. OCP Functional Diagram

16.5 Programmable External and Internal Over-Temperature Protection

Programmable external and internal over-temperature protection (OTP) is provided through real-time monitoring by an internal temperature sensor and by sourcing current to a thermistor via CC1, CC2, DP, DM, or GPIO pins for external sensing. The MCU calculates the temperature from the ADC reading, and OTP is triggered when the measured value exceeds the set threshold.

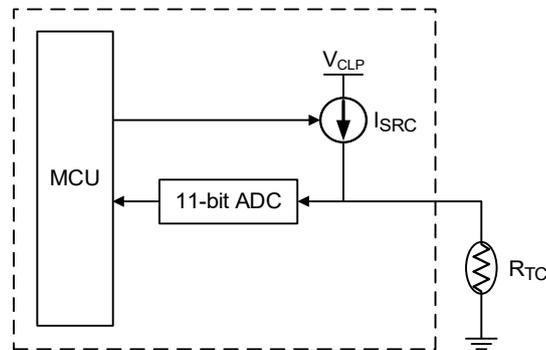


Figure 12. External OTP Functional Diagram

16.6 Thermal Considerations

The junction temperature should never exceed the absolute maximum junction temperature $T_{J(MAX)}$, listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is 125°C. The junction-to-ambient thermal resistance, θ_{JA} , is highly package dependent. For a WQFN-16L 4x4 package, the thermal resistance, θ_{JA} , is 127.44°C/W on a standard JEDEC 51-3 low effective-thermal-conductivity single-layer test board. For a SOP-10 package, the thermal resistance, θ_{JA} , is 137.29°C/W on a standard JEDEC 51-3 low effective-thermal-conductivity single-layer test board. The maximum power dissipation at $T_A = 25^\circ\text{C}$ can be calculated as below:

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (127.44^\circ\text{C/W}) = 0.79\text{W for a WQFN-16L 4x4 package};$$

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (137.29^\circ\text{C/W}) = 0.73\text{W for a SOP-10 package}.$$

The maximum power dissipation depends on the operating ambient temperature for the fixed $T_{J(MAX)}$ and the thermal resistance, θ_{JA} . The derating curves in [Figure 13](#) allow the user to see the effect of rising ambient temperature on the maximum power dissipation.

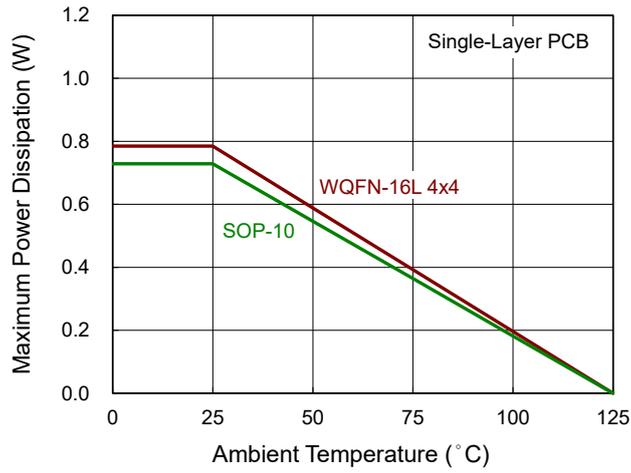
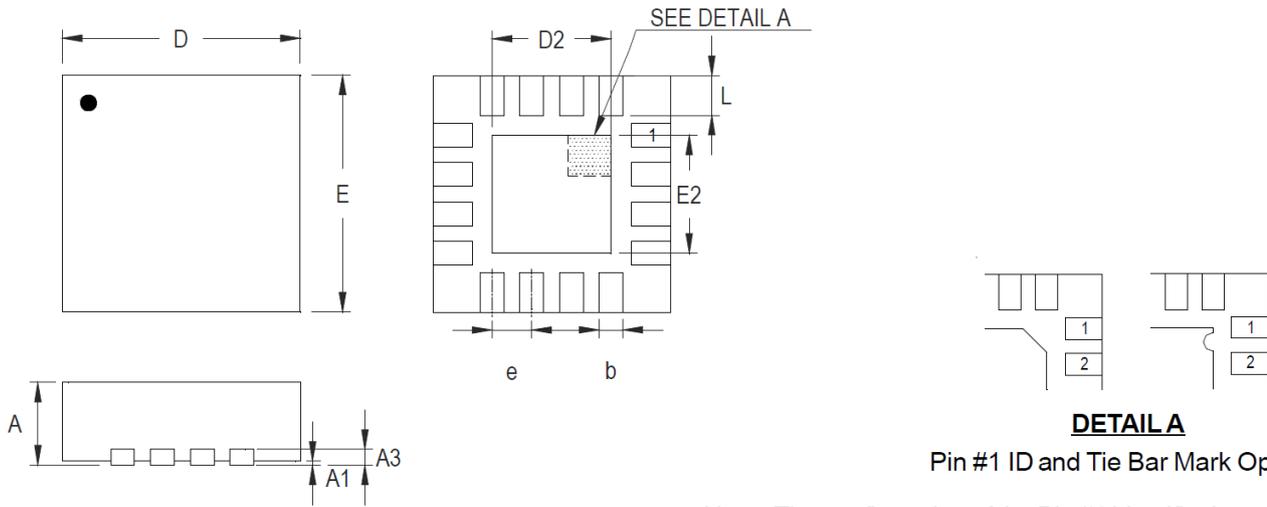


Figure 13. Derating Curves of Maximum Power Dissipation

Note 7. The information provided in this section is for reference only. The customer is solely responsible for designing, validating, and testing any applications incorporating Richtek's product(s). The customer is also responsible for applicable standards and any safety, security, or other requirements.

17 Outline Dimension

17.1 WQFN-16L 4x4 Package



DETAIL A

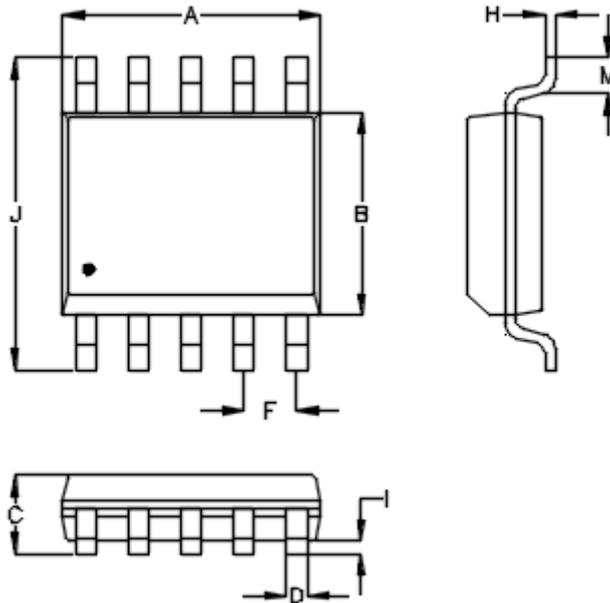
Pin #1 ID and Tie Bar Mark Options

Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.175	0.250	0.007	0.010
b	0.250	0.380	0.010	0.015
D	3.950	4.050	0.156	0.159
D2	2.000	2.450	0.079	0.096
E	3.950	4.050	0.156	0.159
E2	2.000	2.450	0.079	0.096
e	0.650		0.026	
L	0.500	0.600	0.020	0.024

W-Type 16L QFN 4x4 Package

17.2 SOP-10 Package

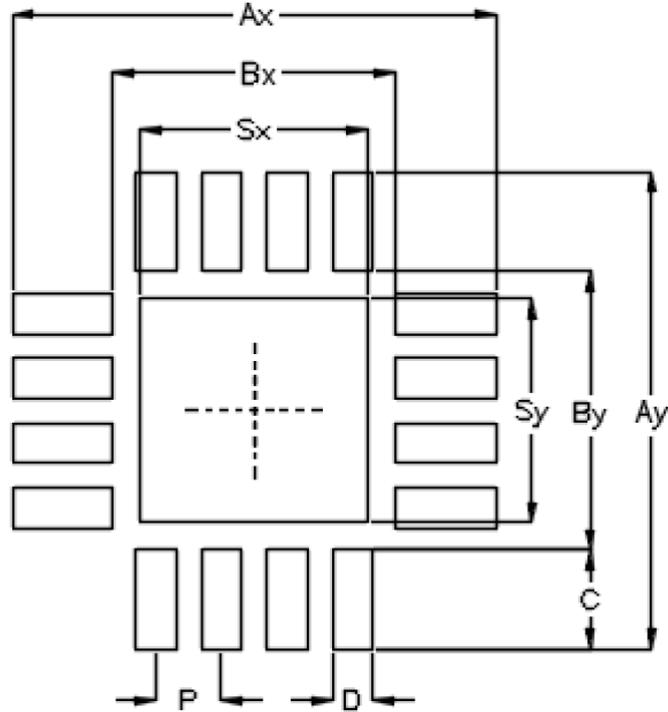


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.800	5.000	0.189	0.197
B	3.800	4.000	0.150	0.157
C	1.300	1.750	0.051	0.069
D	0.300	0.500	0.012	0.020
F	1.000		0.039	
H	0.100	0.250	0.004	0.010
I	0.050	0.250	0.002	0.010
J	5.800	6.200	0.228	0.244
M	0.400	1.270	0.016	0.050

10-Lead SOP Plastic Package

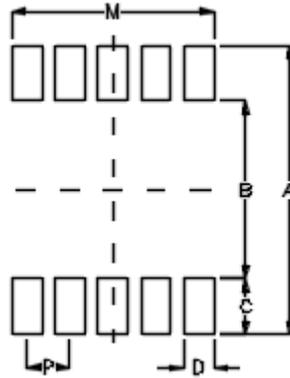
18 Footprint Information

18.1 WQFN-16L 4x4 Package



Package	Number of Pin	Footprint Dimension (mm)									Tolerance
		P	Ax	Ay	Bx	By	C	D	Sx	Sy	
V/W/U/XQFN4*4-16	16	0.65	4.80	4.80	2.80	2.80	1.00	0.40	2.25	2.25	±0.05

18.2 SOP-10 Package

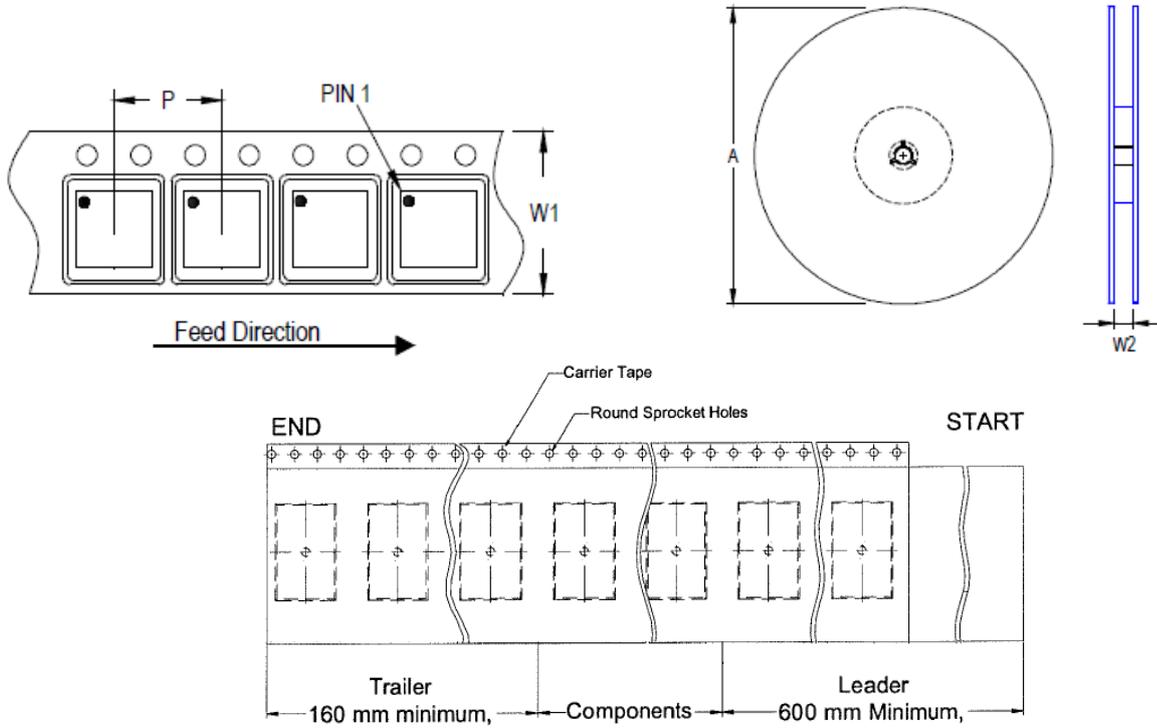


Package	Number of Pin	Footprint Dimension (mm)						Tolerance
		P	A	B	C	D	M	
SOP-10	10	1.00	6.80	4.20	1.30	0.70	4.70	±0.10

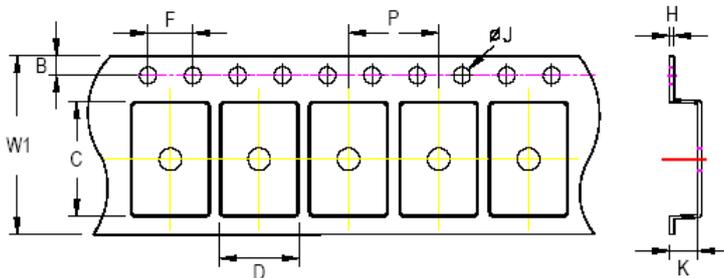
19 Packing Information

19.1 Tape and Reel Data

19.1.1 WQFN-16L 4x4



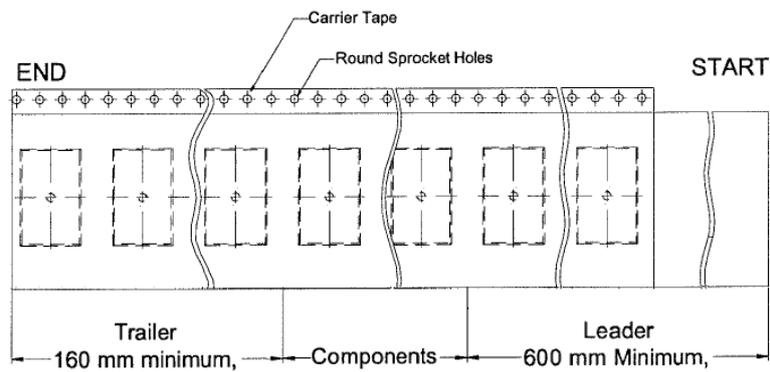
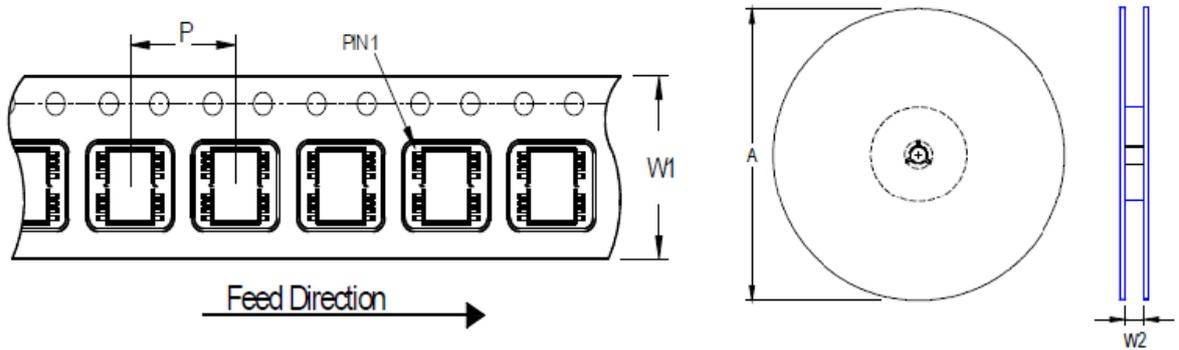
Package Type	Tape Size (W1) (mm)	Pocket Pitch (P) (mm)	Reel Size (A)		Units per Reel	Trailer (mm)	Leader (mm)	Reel Width (W2) Min./Max. (mm)
			(mm)	(in)				
(V, W) QFN/DFN 4x4	12	8	180	7	1,500	160	600	12.4/14.4



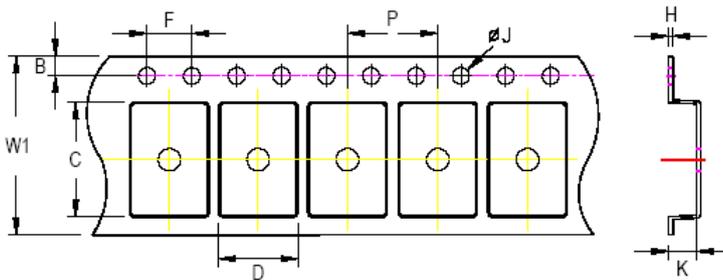
C, D, and K are determined by component size.
The clearance between the components and the cavity is as follows:
- For 12mm carrier tape: 0.5mm max.

Tape Size	W1		P		B		F		ØJ		K		H
	Max	Min	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Max
12mm	12.3mm	7.9mm	7.9mm	8.1mm	1.65mm	1.85mm	3.9mm	4.1mm	1.5mm	1.6mm	1.0mm	1.3mm	0.6mm

19.1.2 SOP-10



Package Type	Tape Size (W1) (mm)	Pocket Pitch (P) (mm)	Reel Size (A)		Units per Reel	Trailer (mm)	Leader (mm)	Reel Width (W2) Min./Max. (mm)
			(mm)	(in)				
SOP-10	12	8	330	13	2,500	160	600	12.4/14.4



C, D, and K are determined by component size.
The clearance between the components and the cavity is as follows:
 - For 12mm carrier tape: 0.5mm max.

Tape Size	W1		P		B		F		ØJ		K		H
	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Max	
12mm	12.3mm	7.9mm	8.1mm	1.65mm	1.85mm	3.9mm	4.1mm	1.5mm	1.6mm	1.9mm	2.2mm	0.6mm	

19.2 Tape and Reel Packing

19.2.1 WQFN-16L 4x4

Step	Photo/Description	Step	Photo/Description
1	 <p>Reel 7"</p>	4	 <p>3 reels per inner box Box A</p>
2	 <p>HIC & Desiccant (1 Unit) inside</p>	5	 <p>12 inner boxes per outer box</p>
3	 <p>Caution label is on backside of AI bag</p>	6	 <p>Outer box Carton A</p>

Container Package	Reel		Box			Carton		
	Size	Units	Item	Reels	Units	Item	Boxes	Unit
(V, W) QFN/DFN 4x4	7"	1,500	Box A	3	4,500	Carton A	12	54,000
			Box E	1	1,500	For Combined or Partial Reel.		

19.2.2 SOP-10

Step	Photo/Description	Step	Photo/Description
1	 Reel 13"	4	 1 reel per inner box Box G
2	 HIC & Desiccant (2 Unit) inside	5	 6 inner boxes per outer box
3	 Caution label is on backside of Al bag	6	 Outer box Carton A

Package \ Container	Reel		Box			Carton		
	Size	Units	Item	Reels	Units	Item	Boxes	Units
SOP-10	13"	2,500	Box G	1	2,500	Carton A	6	15,000

19.3 Packing Material Anti-ESD Property

Surface Resistance	Aluminum Bag	Reel	Cover tape	Carrier tape	Tube	Protection Band
Ω/cm^2	10^4 to 10^{11}					

Richtek Technology Corporation

14F, No. 8, Taiyuan 1st St., Zhubei City,
Hsinchu County 302082, Taiwan (R.O.C.)
Tel: 886-3-5526-789



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20 Datasheet Revision History

Version	Date	Description
00	2025/12/24	First Edition